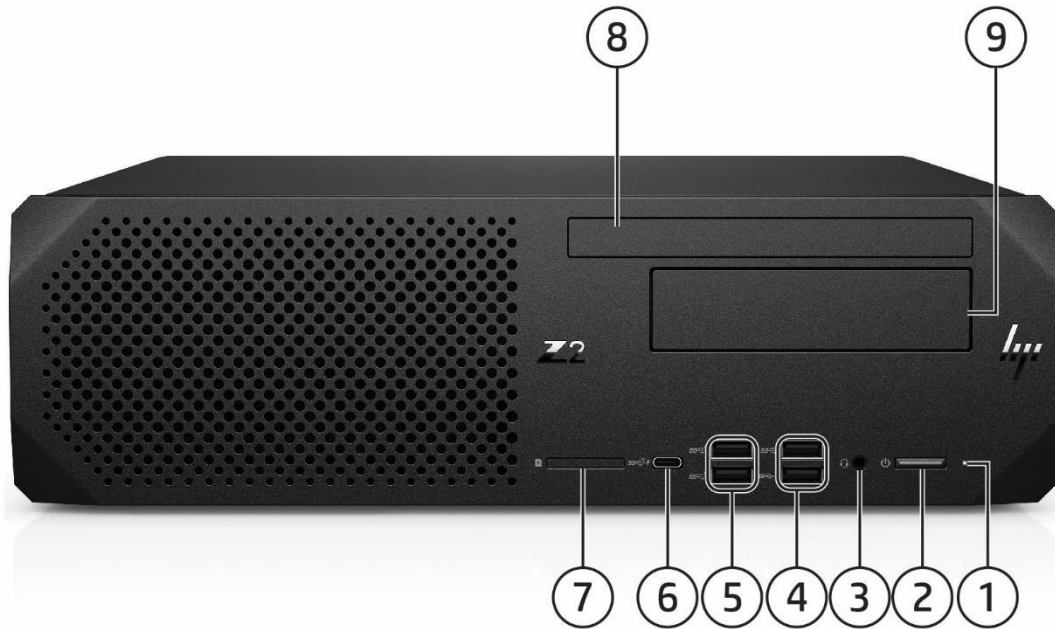


### Overview

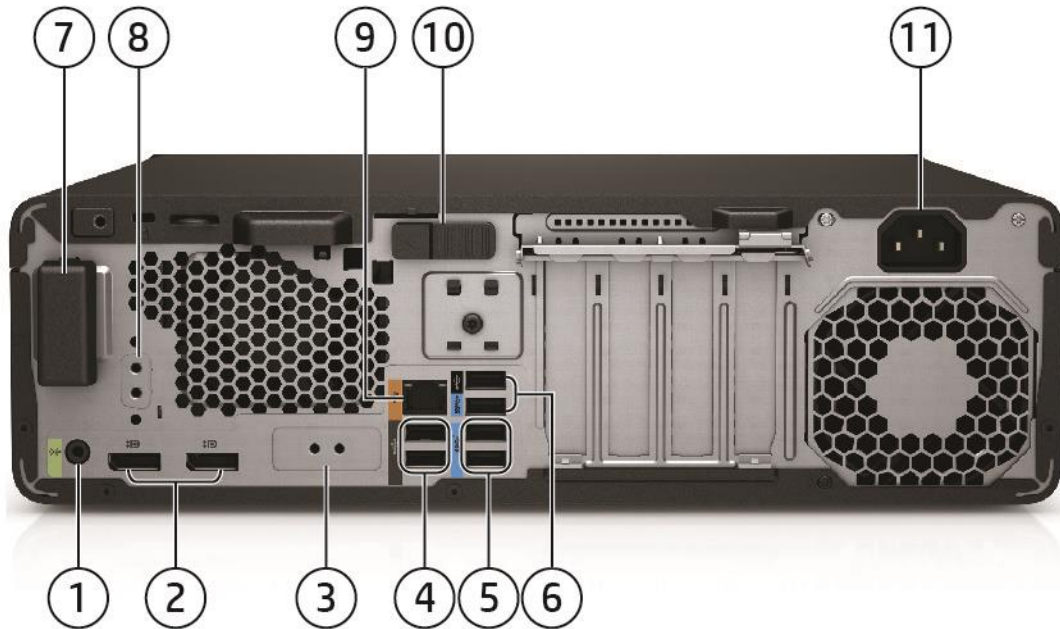
### HP Z2 Small Form Factor G8 Workstation



#### Front View

1. HDD Activity LED
2. Power button
3. Universal audio jack (with CTIA & OMTP headset support)
4. (2) Type-A SuperSpeed USB 5Gbps signaling rate port (1 charge port supports up to 5V/2.1A)
5. (2) Type-A SuperSpeed USB 10Gbps signaling rate port
6. (1) Type-C® SuperSpeed USB 20Gbps signaling rate port (charge supports up to 5V/3A)
7. Media Card Reader 4.0 (optional)
8. Slim ODD bay
9. External/internal shared 3.5" bay

### Overview



#### Rear view

1. Audio line out
2. (2) DisplayPort 1.4
3. Flex I/O module: choose one from the following:  
(1) DisplayPort 1.4, (1) HDMI 2.0b, (1) VGA, (1) Dual Type-A SuperSpeed USB 5Gbps signaling rate, (1) Type-C® SuperSpeed USB 10Gbps signaling rate (Power Delivery 15W, Alt Mode DisplayPort), (1) 2nd GbE LAN, (1) Thunderbolt 3 with Type-C® SuperSpeed USB4 40Gbps signaling rate\* (cabled to PCIe AIC)
4. (2) Hi-Speed USB 480Mbps signaling rate port
5. (2) Type-A SuperSpeed USB 10Gbps signaling rate port
6. (1) Type-A SuperSpeed USB 5Gbps signaling rate port  
(1) Hi-Speed USB 480Mbps signaling rate port
7. WLAN Antenna (optional)
8. 2nd serial port (optional)
9. RJ-45
10. Release latch
11. Power connector

\*Maximum speed requires DisplayPort™ and PCIe aggregation.

**NOTE:** All onboard **Display support DP1.4/HBR2** when video output is via Intel Graphics.

**Note:** Flex I/O module **Display support DP1.4/HBR3**, resolution support up to 5120x3200 24bpp @60Hz

**NOTE:** TBT 3 will be available in Q3, 2021

### Supported Components

#### Form Factor

Small Form Factor

#### Operating Systems

Preinstalled:

- Windows 11 Pro<sup>2</sup>
- Windows 11 Pro for Workstations<sup>2</sup>
- Windows 11 Home - HP recommends Windows 11 Pro for business<sup>2</sup>
- Windows 10 Pro<sup>1,2</sup>
- Windows 10 Pro for Workstations<sup>1,2</sup>
- Windows 10 Home - HP recommends Windows 11 Pro for business<sup>1,2</sup>
- Linux<sup>®</sup>-ready<sup>3</sup>
- Ubuntu Linux 20.04 LTS<sup>4</sup>
- Red Hat<sup>®</sup> Enterprise Linux<sup>®</sup> (RHEL) Workstation – paper license (1yr) only (not preinstalled)

Web-supported only:

- Windows 10 Enterprise 64<sup>2</sup>

Supported Version:

- HP tested Windows 10, versions 1909, 2004, and 20H2 on this platform. For testing information on newer versions of Windows 10, please see: <https://support.hp.com/document/c05195282>.

<sup>1</sup> Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

<sup>2</sup> Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

**NOTE:** Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows<sup>®</sup> 8 or Windows 7 operating system on products configured with Intel<sup>®</sup> and AMD<sup>®</sup> 7th generation and forward processors or provide any Windows<sup>®</sup> 8 or Windows 7 drivers on <http://www.support.hp.com>. A full list of HP products and the Windows 10 versions tested is available on the HP support website. <https://support.hp.com/us-en/document/c05195282>

<sup>3</sup> For detailed Linux<sup>®</sup> OS/hardware information, see: [http://www.hp.com/support/linux\\_hardware\\_matrix](http://www.hp.com/support/linux_hardware_matrix)

<sup>4</sup> Ubuntu Linux 20.04 LTS available Q3, 2021

#### Available Processors

Name	Cores	Clock Speed (GHz)	Intel <sup>®</sup> Turbo Boost Technology <sup>3</sup>	Cache (MB)	Memory Speed (MT/s)	Hyper-Threading	Integrated Graphics	Featuring Intel <sup>®</sup> vPro <sup>®</sup> Technology <sup>4</sup>	16GB Intel <sup>®</sup> Optane <sup>™</sup> memory <sup>2</sup>	TDP (W)
Intel <sup>®</sup> Core <sup>™</sup> i9 11900K Processor	8	3.5	5.2	16	3200	Y	Intel <sup>®</sup> UHD Graphics 750	Y	Y	125
Intel <sup>®</sup> Core <sup>™</sup> i9 11900F Processor	8	2.5	5.1	16	3200	Y	N/A	N/A	Y	65
Intel <sup>®</sup> Core <sup>™</sup> i9 11900 Processor	8	2.5	5.1	16	3200	Y	Intel <sup>®</sup> UHD Graphics 750	Y	Y	65

### Supported Components

Intel® Core™ i7 11700K Processor	8	3.6	5	16	3200	Y	Intel® UHD Graphics 750	Y	Y	125
Intel® Core™ i7 11700 processor	8	2.5	4.9	16	3200	Y	Intel® UHD Graphics 750	Y	Y	65
Intel® Core™ i5 11600K processor	6	3.9	4.9	12	3200	Y	Intel® UHD Graphics 750	Y	Y	125
Intel® Core™ i5 11600 processor	6	2.8	4.8	12	3200	Y	Intel® UHD Graphics 750	Y	Y	65
Intel® Core™ i5 11500 processor	6	2.7	4.6	12	3200	Y	Intel® UHD Graphics 750	Y	Y	65
Intel® Core™ i5 11400F processor	6	2.6	4.4	12	3200	Y	N/A	N/A	Y	65
Intel® Core™ i5 11400 processor	6	2.6	4.4	12	3200	Y	Intel® UHD Graphics 730	N/A	Y	65
Intel® Xeon® W-1390P processor	8	3.5	5.2	16	3200	Y	Intel® UHD Graphics P750	Y	Y	125
Intel® Xeon® W-1390 processor	8	2.8	5.1	16	3200	Y	Intel® UHD Graphics P750	Y	Y	80
Intel® Xeon® W-1370P processor	8	3.6	5.2	16	3200	Y	Intel® UHD Graphics P750	Y	Y	125
Intel® Xeon® W-1370 processor	8	2.9	5.1	16	3200	Y	Intel® UHD Graphics P750	Y	Y	80
Intel® Xeon® W-1350P processor	6	4	5.1	12	3200	Y	Intel® UHD Graphics P750	Y	Y	125
Intel® Xeon® W-1350 processor	6	3.3	5	12	3200	Y	Intel® UHD Graphics P750	Y	Y	80

1. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

2. Intel® Optane™ memory is sold separately. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Available for HP commercial desktops and notebooks and for select HP workstations (HP Z240 Tower/SFF, Z2 Mini, ZBook Studio, 15 and 17 G5) and requires a SATA HDD, 7th Gen or higher Intel® Core™ processor or Intel® Xeon® processor E3-1200 V6 product family or higher, BIOS version with Intel® Optane™ supported, Windows 10 version 1703 or higher, M.2 type 2280-S1-B-M connector on a PCH Remapped PCIe Controller and Lanes in a x2 or x4 configuration with B-M keys that meet NVMe™ Spec 1.1, and an Intel® Rapid Storage Technology (Intel® RST) 15.5 driver.

3. The specifications shown in the Intel® Turbo Boost Technology column represent the maximum turbo frequency with one core active. Turbo boost stepping occurs in 100MHz increments. Processors that do not have turbo functionality are denoted as N/A. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See <http://www.intel.com/technology/turboboost> for more information

4. For full Intel® vPro® functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See <http://intel.com/vpro>

**Color** Black

**Convertibility** The Z2G8 SFF can either be placed flat on the desktop or made to stand on the desk with the optional tower stand.

### Supported Components

<b>Expansion Slots</b> (See system board section for more details)	<p>Slot 1: PCIe Gen4 x16</p> <p>Slot 2: PCIe Gen3 x1</p> <p>Slot 3: PCIe Gen3 x4 - with x4 Connector</p> <p>Slot 4: PCIe Gen3 x4 - with x16 Connector</p>
<b>Expansion Bays</b> (see storage section for more details)	<p>(1) Shared internal/external 3.5" bay</p> <p>(1) Internal 3.5" bay</p> <p>(1) Internal 2.5" bay (for SSD only)</p> <p>(1) Dedicated 9.5mm slim optical disk drive bay</p>
<b>Front I/O</b>	(2) Type-A SuperSpeed USB 5Gbps signaling rate port (1 charge port supports up to 5V/2.1A), (2) Type-A SuperSpeed USB 10Gbps signaling rate port, (1) Type-C® SuperSpeed USB 20Gbps signaling rate port (charge supports up to 5V/3A), (1) SD card reader (optional), 1 universal audio jack
<b>Internal I/O</b>	(1) Hi-Speed USB 480Mbps signaling rate port (1) serial port
<b>Rear I/O</b>	(2) DisplayPort 1.4*, (1) Audio Line out, 1 RJ-45, (3) Hi-Speed USB 480Mbps signaling rate port, (2) Type-A SuperSpeed USB 10Gbps signaling rate port, (1) Type-A SuperSpeed USB 5Gbps signaling rate port, (1) serial (optional), (1) Flex I/O port*** (VGA, HDMI 2.0b, DisplayPort 1.4, Type-C® SuperSpeed USB 10Gbps signaling rate port (Power Delivery 15W, Alt Mode DisplayPort), Dual Type-A SuperSpeed USB 5Gbps signaling rate port, 2nd 1GbE LAN, Thunderbolt 3** with Type-C® SuperSpeed USB4 40Gbps signaling rate**** (cabled to PCIe AIC))
	<p>*All onboard Display support DP1.4/HBR2 when video output is via Intel Graphics.</p> <p>**TBT 3 will be available in Q3, 2021</p> <p>*** Flex I/O module Display support DP1.4/HBR3, resolution support up to 5120x3200 24bpp @60Hz</p> <p>****Maximum speed requires DisplayPort™ and PCIe aggregation.</p>
<b>Interfaces Supported</b>	SD card reader (optional)
<b>On-board RAID Support</b>	RAID 0 RAID 1
<b>Chassis Dimensions (H x W x D)</b>	H: 3.95" [100mm] W: 13.3" [338mm] D: 12.1" [308mm] (Standard desktop orientation)
<b>Packaged Dimensions</b>	H: 8.98" (228mm) W: 15.71" (399mm) D: 19.65" (499mm)
<b>Rack Dimensions</b>	5U
<b>Weight</b>	Exact weights depend upon configuration (System weight only). Starting at 5.4kg (11.9lbs.)
<b>Temperature</b>	Operating: 5° to 35° C (40° to 95° F) Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation Non-operating: -40° to 60° C (-40° to 140° F) Maximum rate of change: 10°C/hr
<b>Humidity</b>	Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb
<b>Maximum Altitude (non-pressurized)</b>	Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

### Supported Components

	Non-operating: 12,192 m (40,000 feet) Maximum operating temperature is reduced as altitude increases. See Temperature for details.
<b>Power Supply</b>	450W wide-ranging, active Power Factor Correction, 90% Efficiency. 260W wide-ranging, active Power Factor Correction, 92% Efficiency. NOTE: The Power Supply Efficiency Report for the 450W 90% Efficiency and 260W 92% Efficiency Power Supply may be found at the following links:  450W PSU: <a href="https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&amp;type=2">https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&amp;type=2</a>  260W PSU: <a href="https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&amp;type=2">https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&amp;type=2</a>
<b>Backup Devices</b>	For a complete listing of compatible DAT tape drives, LTO tape drives and RDX Removable Disk Backup System offerings, please visit <a href="http://www.hp.com/go/connect">http://www.hp.com/go/connect</a>
<b>Chipset</b>	Intel® W580 chipset
<b>Memory</b>	4 DIMM slots, supporting up to 128GB ECC/non-ECC, and up to DDR4 3200 MT/s speeds

### Processors

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
<b>11th Generation Intel® Core Processors*</b>				
Intel® Core™ i9 11900K Processor	Y	N		
Intel® Core™ i9 11900F Processor	Y	N		1
Intel® Core™ i9 11900 Processor	Y	N		
Intel® Core™ i7 11700K Processor	Y	N		
Intel® Core™ i7 11700 processor	Y	N		
Intel® Core™ i5 11600K processor	Y	N		
Intel® Core™ i5 11600 processor	Y	N		
Intel® Core™ i5 11500 processor	Y	N		
Intel® Core™ i5 11400F processor	Y	N		1
Intel® Core™ i5 11400 processor	Y	N		
<b>Intel® Xeon® W Processors</b>				
Intel® Xeon® W-1390P processor	Y	N		
Intel® Xeon® W-1390 processor	Y	N		
Intel® Xeon® W-1370P processor	Y	N		
Intel® Xeon® W-1370 processor	Y	N		
Intel® Xeon® W-1350P processor	Y	N		
Intel® Xeon® W-1350 processor	Y	N		

\* These processors support only non-ECC memory

**NOTE 1:** No iGfx. A discrete graphics card must be purchased at the same time.

### SATA Hard Drives

	Factory Configured	Option Kit	Option Kit Part Number
500GB SATA 7200 rpm 6Gb/s 3.5" HDD	Y	Y	LQ036AA
1TB SATA 7200 rpm 6Gb/s 3.5" HDD	Y	Y	LQ037AA
2TB SATA 7200 rpm 6Gb/s 3.5" HDD	Y		TBD
1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Y	Y	WOR10AA

### Supported Components

2TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Y	Y	Z2274AA
4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Y	Y	K4T76AA
8TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Y	Y	Z2273AA
500GB SATA 7.2K SED SFF HDD	Y	Y	D8N29AA

**NOTE:** SATA HDDs installed in a 3.5" external/internal bay are only supported with a 65W CPU cooler.

### PCIe Solid State Drives

	Factory Configured	Option Kit	Option Kit Part Number
HP ZTurbo PCIe-4X4 1TB TLC Z2 G8 TWR/SFF SSDKit	Y	Y	201F5AA/AT
HP ZTurbo PCIe-4X4 256GB SED Z2 G8 TWR/SFF SSDKit	Y	Y	201F6AA
HP ZTurbo PCIe-4X4 256GB TLC Z2 G8 TWR/SFF SSDKit	Y	Y	201F7AA/AT
HP ZTurbo PCIe-4X4 2TB TLC Z2 G8 TWR/SFF SSDKit	Y	Y	201F8AA
HP ZTurbo PCIe-4X4 512GB SED Z2 G8 TWR/SFF SSDKit	Y	Y	201F9AA
HP ZTurbo PCIe-4X4 512GB TLC Z2 G8 TWR/SFF SSDKit	Y	Y	201G0AA/AT
Z Turbo 1TB 2280 PCIe-Gen4x4 Self Encrypted OPAL2 TLC M.2 Z2 SSD	Y	Y	223A3AA/AT
Z Turbo 2TB 2280 PCIe-Gen4x4 Self Encrypted OPAL2 TLC M.2 Z2 SSD	Y	Y	223A4AA/AT

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB is reserved for system recovery software.

### Hard Drive Controllers

	Factory Configured	Option Kit
<b><u>Integrated SATA Controller (Z2 G8)</u></b>		
Integrated SATA Controller, RAID 0,1 supported: 4x 6 Gb/s ports	Y	
<b><u>Factory integrated RAID on motherboard for SATA drives</u></b>		
RAID 0 Data Configuration	Y	
RAID 1 Data Configuration	Y	
<b><u>Factory integrated RAID on motherboard for Z Turbo Drive</u></b>		
RAID 0 Data Configuration	Y	
RAID 1 Data Configuration	Y	

**NOTE:** SATA hardware RAID is not supported on Linux® systems. The Linux® kernel, with built-in software RAID, provides excellent functionality and performance. It is a good alternative to hardware-based RAID. All drives must be identical in type and capacity. Boot volume/RAID array must be less than 2 TB

**NOTE:** Requires identical drives (speeds, capacity, and interface).

**NOTE:** The HP Z2 Tower G8 Workstation is capable of configuring up to 2 Z Turbo Drives. By default, the Z Turbo Drive configured will be installed in the M.2 storage slot on the system's motherboard.

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows 10) of system disk is reserved for system recovery software.

### Supported Components

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards
<b>Graphics Cable Adapters</b>	HP DisplayPort To HDMI True 4k Adapter	Y	Y	2JA63AA	
	HP Single miniDP-to-DP Adapter Cable	Y	Y	2MY05AA	
	HP DisplayPort To DVI-D Adapter	Y	Y	FH973AA	
	HP DisplayPort To VGA Adapter	Y	Y	AS615AA	
	HP USB-C to DisplayPort Adapter	Y	Y	4SH08AA	
	HP USB-C to HDMI Adapter	Y	Y	4SH07AA	
	HP USB-C to VGA Adapter	Y	Y	4SH06AA	
<b>Entry 3D</b>	NVIDIA® Quadro® P400 2GB Graphics	Y	Y	1ME43AA/AT	2
	NVIDIA® T400 2 GB GDDR6 LP Blower Fan 3mDP PCIe x16 Graphics	Y	Y	340K8AA	2
	NVIDIA® T600 4 GB GDDR6 LP Blower Fan 4mDP PCIe x16 Graphics	Y	Y	340K9AA	2
<b>Mid-range 3D</b>	AMD Radeon™ Pro WX 3200 4GB Graphics	Y	Y	6YT68AA/AT	1
	NVIDIA® T1000 4GB Graphics	Y	Y	20X22AA/AT	1
<b>Ultra High-End 3D</b>	NVIDIA® Quadro® RTX 3000 6GB Graphics	Y		TBD	1

Memory		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP 4GB (1x4GB) DDR4-3200 nECC UDIMM	Y	Y	141J1AA/AT	2,4
	HP 8GB (2x4GB) DDR4-3200 nECC UDIMM	Y	N		
	HP 8GB (1x8GB) DDR4-3200 nECC UDIMM	Y	Y	141J4AA/AT	2,4
	HP 8GB (1x8GB) DDR4-3200 ECC UDIMM	Y	Y	141J3AA/AT	1,2,4
	HP 16GB (2x8GB) DDR4-3200 nECC UDIMM	Y	N		
	HP 16GB (2x8GB) DDR4-3200 ECC UDIMM	Y	N		1
	HP 16GB (1x16GB) DDR4-3200 nECC UDIMM	Y	Y	141H3AA/AT	2,4
	HP 16GB (1x16GB) DDR4-3200 ECC UDIMM	Y	Y	141H2AA/AT	1,2,4
	HP 24GB (3x8GB) DDR4-3200 nECC UDIMM	Y	N		
	HP 24GB (3x8GB) DDR4-3200 ECC UDIMM	Y	N		1
	HP 32GB (4x8GB) DDR4-3200 nECC UDIMM	Y	N		3
	HP 32GB (4x8GB) DDR4-3200 ECC UDIMM	Y	N		1,3
	HP 32GB (2x16GB) DDR4-3200 nECC UDIMM	Y	N		
	HP 32GB (2x16GB) DDR4-3200 ECC UDIMM	Y	N		1
	HP 32GB (1x32GB) DDR4-3200 nECC UDIMM	Y	N	141H9AA	2,4
	HP 32GB (1x32GB) DDR4-3200 ECC UDIMM	Y	N	141H7AA	1,2,4
	HP 64GB (4x16GB) DDR4-3200 nECC UDIMM	Y	N		3
	HP 64GB (4x16GB) DDR4-3200 ECC UDIMM	Y	N		1,3
	HP 64GB (2x32GB) DDR4-3200 nECC UDIMM	Y	N		3
	HP 64GB (2x32GB) DDR4-3200 ECC UDIMM	Y	N		1,3
	HP 128GB (4x32GB) DDR4-3200 nECC UDIMM	Y	N		3



### Supported Components

HP 128GB (4x32GB) DDR4-3200 ECC UDIMM      Y      N      1,3

**NOTES:**

1. Intel® Xeon® can support either ECC or non-ECC memory; Intel® Core™ i5/i7/i9 processors only support non-ECC memory.
2. Two channels of DDR4 memory are supported. To realize full performance at least one DIMM must be inserted into each channel.
3. The maximum speed supported by Intel on this configuration is 2933 MT/s
4. For Option Kits, only 2666Mhz can be guaranteed.

**Note: When more than one memory slot is populated, symmetric configurations are required for 2 DIMMs per channel. Mix of different part numbers or mix of single and dual ranks within a channel is not allowed.**

### Optical and Removable Storage

	Factory Configured	Option Kit	Option Kit Part Number
HP SD card reader Z2 SFF	Y	Y	16U37AA/AT
HP 9.5mm Slim DVD Writer	Y	Y	4L5J9AA
HP DP25 Removable 2.5" HDD Frame/Carrier	Y	Y	W3J84AA
HP 9.5mm Slim DVD-ROM Drive	Y	Y	4L5J8AA
HP QX310 3.5in Frame/Carrier	Y	Y	4D9X2AA

**NOTE:** With Blu-ray, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

**NOTE:** When assembled correctly, the Slim ODD is not flush with the Z2 G8 SFF bezel. It is indented by approximately 7.2mm.

**NOTE:** SATA HDDs installed in a removeable Frame/Carrier are only supported with a 65W CPU cooler.

### Networking and Communications

	Factory Configured	Option Kit	Option Kit Part Number
Integrated Intel® I219LM PCIe GbE Controller (Intel® vPro® with Intel® AMT 15.0)	Y	N	
HP 1GbE LAN Flex Port 2020	Y	Y	141J6AA/AT
Aquantia AQN108 1-Port 5GbE NIC	Y	Y	1PM63AA
Intel Ethernet I350-T4 4-Port 1Gb NIC	N	Y	W8X25AA
Intel X550 10GBASE-T Dual Port NIC	Y	Y	1QL46AA
Intel Ethernet Network Adapter I225-T1*	Y	Y	406L9AA
Intel Ethernet I350-T2 2-Port 1Gb NIC	Y	Y	V4A91AA
Intel Wi-Fi 6 AX201 BT5 M.2 non-vPro**	Y	N	

\*Planned to be available in Q3,2021

\*\* Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

**NOTE:** The integrated network connection is required to support Intel® vPro® Technology.

**NOTE:** If AMT is provisioned, then network teaming with the integrated LAN port is not possible.

**NOTE:** "Gigabit" Ethernet indicates compliance with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

### Supported Components

Input Devices	Factory Configured	Option Kit	Option Kit Part Number
HP Premium Wireless Keyboard	Y	Y	Z9N41AA/AT
HP USB 320K Keyboard	Y	Y	9SR37AA
HP USB Business Slim Wired SmartCard CCID Keyboard	Y	N	
HP PS/2 Business Slim Keyboard	N	Y	N3R86AA
HP USB Premium Wired Keyboard PROMO	Y	Y	Z9N40AT
HP 320M Wired Mouse	Y	Y	9VA80AA
HP USB Premium Mouse	Y	Y	1JR32AA
HP Wireless Premium Mouse	Y	Y	1JR31AA
HP Promo PS/2 Mouse	N	Y	QY775AT
HP Wired Desktop 320MK Mouse and Keyboard	N	Y	9SR36AA
HP Creator 935 Black Wireless Mouse	N	Y	1DOK8AA

Other Hardware	Factory Configured	Option Kit	Option Kit Part Number
HP Single TBT3 Type C and USB4 PCIe x4 Card <sup>1</sup>	Y	N	
HP Z2 Internal Serial Port and PS/2 Port	Y	Y	141K9AA/AT
HP Z2 Power Cord Kit	Y	Y	1N1D5AA
HP Z2 2nd serial port adapter	Y	Y	141K9AA/AT
HP Z2 SFF Dust Filter	Y	Y	141L0AA/AT
HP Z2 SFF Dust Filter and bezel	Y	Y	141L1AA/AT
HP Z2 Internal Serial Port and PS/2 Port	Y	Y	141K9AA/AT
HP PCIe x1 Parallel Port Card	Y	Y	N1M40AA
HP DP Flex Port 2020	Y	Y	141J7AA/AT
HP Dual USB-A 3.2 Gen1 Flex 2020	Y	Y	141J8AA/AT
HP Front Type-C SuperSpeed USB 20Gbps port	Y	Y	201F4AA/AT
HP HDMI Flex Port 2020	Y	Y	141K1AA/AT
HP USB-C 3.2 Gen2 Alt Flex Port 2020	Y	Y	141K6AA/AT
HP VGA Flex Port 2020	Y	Y	141K7AA/AT

<sup>1</sup>Available in Q3, 2021

Software	Factory Configured	Option Kit	Support Notes
HP Performance Advisor	Y	N	1
HP PC Hardware Diagnostics UEFI (Windows OS only)	Y	N	2
HP PC Hardware Diagnostics Windows	Y	N	
HP Sure Sense	Y	N	
HP Notifications	Y	N	
HP Desktop Support Utility	Y	N	
HP Documentation	Y	N	
HP Image Assistant	N	N	
HP Support Assistant	N	N	

### Supported Components

HP QuickDrop	Y	N
myHP	Y	N

**Notes:**

1. Supports, and preinstalled with Windows 10 or Windows 11 only. Also available as a free download from <http://www.hp.com/go/performanceadvisor>
2. Windows OS only

### Application Software

	Factory Configured	Option Kit	Support Notes
HP ZCentral Remote Boost	N	N	
Data Science Stack	Y	N	1,2
WSL2/Ubuntu Data Science Stack	Y	N	1,3

\*Not all Application Software for Z Desktop Workstations is included with purchase.

**Note 1:** Only available with NVIDIA graphics cards selections.

**Note 2:** Only available with Ubuntu 20.04 LTS preinstall.

**Note 3:** Only available with Windows 10 Pro/Pro for Workstations or Windows 11 Pro/Pro for Workstations.

### Operating Systems

Windows 11 Pro<sup>2</sup>  
 Windows 11 Pro for Workstations<sup>2</sup>  
 Windows 11 Home - HP recommends Windows 11 Pro for business<sup>2</sup>  
 Windows 10 Pro<sup>1,2</sup>  
 Windows 10 Pro for Workstations<sup>1,2</sup>  
 Windows 10 Home - HP recommends Windows 11 Pro for business<sup>1,2</sup>  
 Linux<sup>®</sup>-ready  
 Ubuntu Linux 20.04 LTS  
 Red Hat<sup>®</sup> Enterprise Linux<sup>®</sup> (RHEL) Workstation – paper license (1 yr) only (not preinstalled)

**NOTE 1:** Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

**NOTE 2:** Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

**NOTE:** Windows 11 Pro/Pro for Workstations and Windows 10 Pro/Pro for Workstations is available with Windows Subsystem for Linux<sup>®</sup> (WSL 2).

**NOTE:** For detailed OS/hardware information for Linux, see: [http://www.hp.com/support/linux\\_hardware\\_matrix](http://www.hp.com/support/linux_hardware_matrix)

### HP BIOS

Key features of the HP BIOS include:

### Supported Components

- Deployment and manageability – HP BIOS provides several technologies that help integrate the HP Z2 G8 Workstation into the enterprise, such as PXE, remote recovery, remote configuration, remote control, and BIOS (F10) Setup support for 15 languages.
- Network firmware updates – Update your BIOS via the cloud or standardize on a BIOS version hosted on an Enterprise network.
- Stability – HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- UEFI specification version 2.7
- Absolute Persistence agent – For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
- Thermal and power management – The HP BIOS provides and enables thermal and power management technologies so component temperatures are managed for high reliability and to assist in operating the HP Workstation computer in any enterprise environment.
- Acoustic performance – Industry leading acoustic emissions across the range of operating conditions.
- Serviceability – HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery – HP BIOS provides numerous ways to upgrade HP Workstation computers, including BIOS updates from within Windows (HP Firmware Update and Recovery), Capsule update, HP Client Manager, and fail-safe recovery. In addition, the HP BIOS Configuration Utility enables replication of BIOS settings within Windows while the Replicated Setup feature provides the same capability within BIOS (F10) Setup. The BIOS Configuration Utility is available from the HP support website.
- HP BIOS uses PKI signing of the BIOS for trusted BIOS upgrades and recovery

#### Additional HP BIOS Features:

- Power-On password – Helps prevent an unauthorized user from powering on the system.
- Administrator password – Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated and changes cannot be made to BIOS settings using BIOS Setup or under the OS.
- S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:
  - Power to expansion connectors / slots
  - Most Wake events other than power buttons and WOL(Wake on LAN supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled )
  - USB charging ports

#### HP Sure Start Gen7 Start

- BIOS Integrity checking – Sure Start protection ensures that only trusted BIOS code is executed and not rootkits, viruses and malware. Verification is done upon boot up, shutdown and while the system is on.
- Sure Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability. Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability.
- Protecting beyond BIOS – Integrity checking and repair is extended to other data that should be protected such as network configuration parameters, platform specific information (i.e. system IDs), secure boot credentials, and other code the system needs to boot.
- Audit enabled – System Audit via Sure Start Event Logs capture data such as incident, repair date and time for troubleshooting and investigating

### Supported Components

**NOTE:** HP Sure Start Gen7 is available on HP Workstation products equipped with Intel® 11th generation processors.

---

### Supported Components

#### SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

##### BIOS

- HP BIOSphere Gen6<sup>1</sup>
- BIOS Update via Network
- HP Secure Erase<sup>2</sup>
- Absolute Persistence Module<sup>3</sup>
- Pre-boot Authentication
- HP Wake on WLAN
- HP DriveLock & Automatic DriveLock

##### Software

- HP Support Assistant
- HP Image Assistant
- HP Desktop Support Utility
- HP Documentation
- HP Notifications
- HP PC Hardware Diagnostics UEFI
- HP PC Hardware Diagnostics Windows
- HP Performance Advisor<sup>4</sup>
- ZCentral Remote Boost<sup>5</sup>
- My HP
- HP QuickDrop

##### Manageability Features

- HP Driver Packs<sup>6</sup>
- HP System Software Manager (SSM)
- HP BIOS Config Utility (BCU)
- HP Manageability Integration Kit Gen4<sup>7</sup>
- HP Smart Support<sup>16</sup>

##### Client Security Software

- HP Client Security Manager Gen7<sup>8</sup> including:  
(including Credential Manager, HP Password Manager<sup>9</sup>, HP Spare Key)
- HP Power On Authentication
- Microsoft Defender<sup>10</sup>

##### Security Management

- HP Sure Click<sup>11</sup>
- HP Sure Start Gen7<sup>12</sup>
- HP Sure Run Gen4<sup>13</sup>
- HP Sure Sense<sup>14</sup>
- HP Sure Recover Gen4<sup>15</sup>
- HP Pro Wolf Security

[1] HP BIOSphere Features may vary depending on the platform and configurations.

[2] HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.

[3] Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: <http://www.absolute.com/company/legal/agreements/computrace-agreement>. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers

### Supported Components

must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

[4] HP Performance Advisor Software - HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at:

<https://www8.hp.com/us/en/workstations/performance-advisor.html>

[5] HP Z Central Remote Boost Software does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. Zcentral Remote Boost requires Windows, RHEL (7 or 8), UBUNTU 18.04 LTS, or HP ThinPro 7 operating systems. MacOS (10.13 or newer) operating system is only supported on the receiver side. Requires network access. The software is available for download at [hp.com/ZCentralRemoteBoost](http://hp.com/ZCentralRemoteBoost).

[6] HP Driver Packs not preinstalled, however available for download at <http://www.hp.com/go/clientmanagement>.

[7] HP Manageability Integration Kit can be downloaded from

<http://www8.hp.com/us/en/ads/clientmanagement/overview.html>

[8] HP Client Security Manager Gen6 requires Windows and is available on the select HP Elite and Pro PCs.

[10] Microsoft Defender Opt in and internet connection required for updates.

[11] HP Sure Click requires Windows 10/11 Pro or Enterprise. See [https://bit.ly/2PrLT6A\\_SureClick](https://bit.ly/2PrLT6A_SureClick) for complete details.

[12] HP Sure Start is available on select HP PCs and requires Windows 10/11.

[13] HP Sure Run is available on HP Workstation products equipped with 8th generation Intel® or AMD® processors.

[14] HP Sure Sense requires Windows 10/11 Pro or Enterprise. See product specifications for availability.

[15] HP Sure Recover is available on select HP PCs and requires an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.

[16] HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: <http://www.hp.com/smart-support>. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.

### System Technical Specifications

#### System Board

<b>System Board Form Factor</b>	Customized PCB 30.124 x 24.38 mm (11.86 x 9.6 inches)
<b>Processor Socket</b>	Single LGA-1200
<b>CPU Bus Speed</b>	DMI
<b>Chipset</b>	Intel® PCH W580
<b>Super I/O Controller</b>	Nuvoton SIO18
<b>Memory Expansion Slots</b>	4 DDR4 memory slots
<b>Memory Type Supported</b>	DDR4, UDIMM (Unbuffered), ECC& non-ECC
<b>Memory Modes</b>	Non-Interleaved for single channel. Interleaved when both channels are populated.
<b>Memory Speed Supported</b>	Up to 3200MT/s DDR4
<b>Memory Protection</b>	ECC available on data
<b>Maximum Memory</b>	128GB <sup>1</sup>
<b>Memory Configuration (Supported)</b>	4GB, 8GB, 16GB and 32GB non-ECC/8GB, 16GB and 32GB ECC unbuffered DIMMs are supported. ECC and non-ECC memory DIMMs cannot be mixed in the same system
<b>PCI Express Connectors<sup>2</sup></b>	(1) PCI Express Gen4 slot x16 mechanical/ x16 electrical (full height, full length) (1) PCI Express Gen3 slot x1 mechanical/ x1 electrical (full height, full length, open-ended) (1) PCI Express Gen3 slot x4 mechanical/ x4 electrical (full height, full length, open-ended) (1) PCI Express Gen3 slot x16 mechanical/ x4 electrical (full height, full length) (1) M.2 2280 Storage (PCIe Gen4 x4) <sup>2</sup> (1) M.2 2280 Storage (PCIe Gen3 x4) <sup>2</sup> (1) M.2 2230 WLAN (PCIe Gen3 x1+ Intel CNVi) <sup>2</sup>

**NOTE:** The PCIe Gen 4 x16 slot is meant for HP qualified cards, configured or after market. HP does not provide warranty support for 3rd party cards.

#### Supported Drive Interfaces

<b>SATA</b>	Integrated (4) Serial ATA interfaces (6Gb/s SATA).
<b>Integrated Graphics</b>	Intel® UHD Graphics 730 (on Core i5-11400 processors); Intel® UHD Graphics 750 (on Core i5/i7/i9 processors); Intel® Integrated Graphics P750 for Xeon processors Based on Unified Memory Architecture (UMA) - a region of system memory is reserved and dedicated to the graphics display. Support for Microsoft DirectX 12, OpenGL 4.6 and OpenCL 3.0 on Intel® UHD Graphics 730/750; Based on Unified Memory Architecture (UMA) - a region of system memory is reserved and dedicated to the graphics display. Support for Microsoft DirectX 12, OpenGL 4.6 and OpenCL 3.0 on Intel® UHD Graphics P750; 2 DP 1.4 graphics ports integrated in motherboard; Supports up to three simultaneous displays across DisplayPort*/HDMI*/DVI outputs. Max. resolution supported on onboard DP 1.4/HBR2 ports: 4096x2304 @ 60Hz, 24bpp Max. resolution supported on FlexIO DP 1.4/HBR3 port: 5120x3200 @60Hz, 24bpp
<b>Network Controller</b>	Integrated Ethernet PHY Connection I219LM. Management capabilities: WOL, PXE 2.1 and AMT 15
<b>Serial</b>	Yes- requires optional Serial Port Adapter Kit
<b>2nd Serial</b>	Yes- requires optional Serial Port Adapter Kit



### System Technical Specifications

<b>USB Connector(s)</b>	<b>Front</b>	2 Type-A SuperSpeed USB 5Gbps signaling rate port (1 charge port supports up to 5V/2.1A); 2 Type-A SuperSpeed USB 10Gbps signaling rate port; 1 Type-C® SuperSpeed USB 20Gbps signaling rate port (charge supports up to 5V/3A)
	<b>Rear</b>	3 High-speed USB 480Mbps signaling rate port; 1 Type-A SuperSpeed USB 5Gbps signaling rate port; 2 Type-A SuperSpeed USB 10Gbps signaling rate port; Flex I/O option: 1 Type-C® SuperSpeed USB 10Gbps signaling rate (Power Delivery 15W, Alt Mode DisplayPort); 1 Dual Type-A SuperSpeed USB 5Gbps signaling rate 1 Hi-Speed USB 480Mbps signaling rate port
	<b>Internal</b>	
<b>HD Integrated Audio</b>		Realtek ALC3205
<b>Flash ROM</b>		Yes
<b>CPU Fan Header</b>		Yes
<b>Memory Fan Header</b>		None
<b>Chassis Fan Header</b>		1 Rear System Chassis Fan Header, 1 Graphic chassis Fan Header.
<b>Front PCI Fan Header</b>		None
<b>Front Control Panel/Speaker Header</b>		Yes
<b>CMOS Battery Holder - Lithium</b>		Yes
<b>Integrated Trusted Platform Module</b>		Integrated TPM 2.0 (Infineon SLB9670) Convertible to FIPS 140-2 Certified mode through firmware v7.85 The TPM module disabled where restricted by law, i.e. Russia.
<b>Power Supply Headers</b>		Yes
<b>Power Switch, Power LED &amp; Hard Drive LED Header</b>		Yes
<b>Clear Password Jumper</b>		None
<b>Keyboard/Mouse</b>		USB or PS/2 (option)
<b>Power Supply</b>		260W EPA92 and 450W EPA90

<sup>1</sup>Maximum memory capacities assume 64-bit operating systems, such as Genuine Windows® 10 Professional 64 bit, Red Hat Linux 64-bit. 32-bit Windows Operating Systems support up to 4 GB.

<sup>2</sup>M.2 storage supports compatible devices up to 80mm

System Configurations							
<b>Z2G8 SFF Configuration #1</b>	<b>Processor Info</b>	Intel Core i5- 11400 2.60GHz 6C65W					
	<b>Memory Info</b>	8GB (1x 8GB) 3200 MHz DDR4 non-ECC					
	<b>Graphics Info</b>	Intel® UHD Integrated Graphics 730					
	<b>Disks/Optical/Floppy</b>	1x SATA 1TB 7.2k rpm / 1x 9.5mm Slim ODD					
	<b>PSU</b>	260W					
	<b>Other</b>						
<b>Energy Consumption (Watts)</b>		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows long Idle (S0)	15.842		15.996		15.63	

### System Technical Specifications

	Windows short Idle (S0)	16.668		16.738		16.437	
	Windows Busy Typ (S0)	96.264		95.623		94.155	
	Windows Busy Max (S0)	94.286		94.628		93.582	
	Sleep (S3)	0.849	0.804	0.862	0.813	0.883	0.842
	Off (S5)	0.518	0.466	0.566	0.473	0.575	0.54
	Zero Power Mode (EuP)	0.218		0.257		0.223	
<b>Heat Dissipation (Btu/hr)</b>		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	54.052904		54.578352		53.32956	
	Windows short Idle (S0)	56.871216		57.110056		56.083044	
	Windows Busy Typ (S0)	328.452768		326.265676		321.25686	
	Windows Busy Max (S0)	321.703832		322.870736		319.301784	
	Sleep (S3)	2.896788	2.743248	2.941144	2.773956	3.012796	2.872904
	Off (S5)	1.767416	1.589992	1.931192	1.613876	1.9619	1.84248
	Zero Power Mode (EuP)	0.743816		0.876884		0.760876	
<b>Z2G8 SFF Configuration #2</b> ENERGY STAR® CERTIFIED	<b>Processor Info</b>	Intel Core i7- 11700 2.50GHz 8C65W					
	<b>Memory Info</b>	16GB (2x 8GB) 3200MHz DDR4 non-ECC					
	<b>Graphics Info</b>	NVIDIA Quadro P400 2GB					
	<b>Disks/Optical/Floppy</b>	1x SATA 256GB SSD / 1x9.5mm Slim ODD					
	<b>PSU</b>	450W					
	<b>Other</b>						
<b>Energy Consumption (Watts)</b>		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows long Idle (S0)	20.619		20.622		20.129	
	Windows short Idle (S0)	21.298		21.456		21.232	
	Windows Busy Typ (S0)	138.407		141.28		144.091	
	Windows Busy Max (S0)	135.898		138.426		140.117	
	Sleep (S3)	0.829	0.781	0.881	0.832	0.979	0.941
	Off (S5)	0.621	0.568	0.648	0.574	0.693	0.656
	Zero Power Mode (EuP)	0.211		0.232		0.229	
<b>Heat Dissipation (Btu/hr)</b>		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	70.352028		70.362264		68.680148	
	Windows short Idle (S0)	72.668776		73.207872		72.443584	
	Windows Busy Typ (S0)	472.244684		482.04736		491.638492	
	Windows Busy Max (S0)	463.683976		472.309512		478.079204	
	Sleep (S3)	2.828548	2.664772	3.005972	2.838784	3.340348	3.210692
	Off (S5)	2.118852	1.938016	2.210976	1.958488	2.364516	2.238272

### System Technical Specifications

	Zero Power Mode (EuP)	0.719932	0.791584	0.781348
<b>Z2G8 SFF Configuration #3</b>	<b>Processor Info</b>	Intel Core i9- 11900K 3.50GHz 8C125W		
	<b>Memory Info</b>	64GB (2x 32GB) 3200MHz DDR4 ECC		
	<b>Graphics Info</b>	NVIDIA Quadro T1000 4 GB		
	<b>Disks/Optical/Floppy</b>	1x SATA 512GB SSD		
	<b>PSU</b>	450W		
	<b>Other</b>			

Energy Consumption (Watts)		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows long Idle (S0)	23.504		23.537		23.095	
	Windows short Idle (S0)	24.304		24.682		24.298	
	Windows Busy Typ (S0)	224.139		225.56		227.168	
	Windows Busy Max (S0)	213.511		222.54		216.214	
	Sleep (S3)	1.152	1.1	1.141	0.862	1.123	1.076
	Off (S5)	0.628	0.593	0.652	0.538	0.553	0.504
	Zero Power Mode (EuP)	0.199		0.232		0.211	

Heat Dissipation (Btu/hr)		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	80.195648		80.308244		78.80014	
	Windows short Idle (S0)	82.925248		84.214984		82.904776	
	Windows Busy Typ (S0)	764.762268		769.61072		775.097216	
	Windows Busy Max (S0)	728.499532		759.30648		737.722168	
	Sleep (S3)	3.930624	3.7532	3.893092	2.941144	3.831676	3.671312
	Off (S5)	2.142736	2.023316	2.224624	1.835656	1.886836	1.719648
	Zero Power Mode (EuP)	0.678988		0.791584		0.719932	

<b>Z2G8 SFF Configuration #4</b> ENERGY STAR® CERTIFIED	<b>Processor Info</b>	Intel Xeon W- 1370P 3.60G 8C125W		
	<b>Memory Info</b>	64GB (2x32GB) 3200MHz DDR4 ECC		
	<b>Graphics Info</b>	AMD Radeon Pro WX 3200 4GB		
	<b>Disks/Optical/Floppy</b>	1x SATA 1TB SSD Z Turbo		
	<b>PSU</b>	450W		
	<b>Other</b>			

Energy Consumption (Watts)		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows long Idle (S0)	16.807		17.025		16.742	
	Windows short Idle (S0)	23.574		23.645		23.392	
	Windows Busy Typ (S0)	234.147		236.01		238.48	
	Windows Busy Max (S0)	228.984		232.11		231.252	

### System Technical Specifications

	Sleep (S3)	1.241	1.206	1.156	0.873	1.254	1.196
	Off (S5)	0.733	0.68	0.646	0.559	0.579	0.537
	Zero Power Mode (EuP)	0.221		0.243		0.219	
<b>Heat Dissipation (Btu/hr)</b>		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	57.345484		58.0893		57.123704	
	Windows short Idle (S0)	80.434488		80.67674		79.813504	
	Windows Busy Typ (S0)	798.909564		805.26612		813.69376	
	Windows Busy Max (S0)	781.293408		791.95932		789.031824	
	Sleep (S3)	4.234292	4.114872	3.944272	2.978676	4.278648	4.080752
	Off (S5)	2.500996	2.32016	2.204152	1.907308	1.975548	1.832244
	Zero Power Mode (EuP)	0.754052		0.829116		0.747228	
	<b>Z2G8 SFF Configuration #5</b>	<b>Processor Info</b>	Intel Xeon W- 1350 3.30GHz 6C80W				
<b>Memory Info</b>		16GB (2x8GB) 3200 MHz DDR4 ECC					
<b>Graphics Info</b>		NVIDIA Quadro RTX 3000 6 GB					
<b>Disks/Optical/Floppy</b>		1x SATA 1TB SSD Z Turbo					
<b>PSU</b>		450W					
<b>Other</b>							

<b>Energy Consumption (Watts)</b>		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows long Idle (S0)	23.509		23.611		23.415	
	Windows short Idle (S0)	24.519		24.808		24.47	
	Windows Busy Typ (S0)	188.034		186.01		184.387	
	Windows Busy Max (S0)	170.716		168.03		165.495	
	Sleep (S3)	1.014	0.981	1.014	0.826	0.956	0.896
	Off (S5)	0.591	0.558	0.654	0.573	0.567	0.517
	Zero Power Mode (EuP)	0.216		0.241		0.196	
<b>Heat Dissipation (Btu/hr)</b>		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	80.212708		80.560732		79.89198	
	Windows short Idle (S0)	83.658828		84.644896		83.49164	
	Windows Busy Typ (S0)	641.572008		634.66612		629.128444	
	Windows Busy Max (S0)	582.482992		573.31836		564.66894	
	Sleep (S3)	3.459768	3.347172	3.459768	2.818312	3.261872	3.057152
	Off (S5)	2.016492	1.903896	2.231448	1.955076	1.934604	1.764004
	Zero Power Mode (EuP)	0.736992		0.822292		0.668752	

**NOTE:** The Power Supply Efficiency report may be found at the following links:

### System Technical Specifications

<https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2>

<b>Operating Voltage Range</b>	90-269 VAC
<b>Rated Voltage Range</b>	100-240 VAC
<b>Rated Line Frequency</b>	50-60 Hz
<b>Operating Line Frequency Range</b>	47-66 Hz
<b>Rated Input Current</b>	6A @ 100-240V
<b>Heat Dissipation</b>	Typical: 444 btu/hr (112 kcal/hr) Maximum: 1484 btu/hr (374 kcal/hr)
<b>ENERGY STAR® certified (Config Dependent)</b>	Yes
<b>CECP Compliant @ 220V</b>	Yes
<b>FEMP Standby Power Compliant</b>	Yes, with Wake-on-LAN disabled: <2W in S4/S5- Power Off
<b>Built-in Self Test (BIST) LED</b>	Yes
<b>Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V)</b>	Yes
<b>Hood Lock Header</b>	Yes
<b>ErP Lot 6- Tier 1 Compliance @ 230V (&lt;1W in S4/S5- Power Off)</b>	Yes
<b>ErP Lot 6- Tier 2 Compliance @ 230V (&lt;0.5W in S4/S5- Power Off)</b>	Yes

Declared Noise Emissions (Entry-level, Mid-level, and High-end configurations; tested on floor)			
<b>System Configuration (Entry level)</b>	<b>Processor Info</b>	Intel® Core™ i9-11900 2.5 GHz 8C CPU	
	<b>Memory Info</b>	64GB DDR4-3200 nECC (4x16GB) RAM	
	<b>Graphics Info</b>	NVIDIA® T1000 4GB	
	<b>Disks/Optical</b>	1 TB SATA 6Gb/s SSD / No Optical /	
	<b>Power Supply</b>	450W PSU	
<b>Declared Noise Emissions</b>		<b>Sound Power (LWAd, bels)</b>	<b>Deskside Sound Pressure (LpAm, decibels)</b>
	<b>Idle</b>	2.98	11.31
	<b>Hard drive Operating (random reads)</b>	3.08	16.4
<b>System Configuration (Mid-level)</b>	<b>Processor Info</b>	Intel® Xeon® processor W-1390 2.8 GHz 8C CPU	
	<b>Memory Info</b>	64GB DDR4-3200 nECC (4x16GB) RAM	
	<b>Graphics Info</b>	NVIDIA® T1000 4GB	
	<b>Disks/Optical</b>	2 x 2TB SATA 7200 rpm 6Gb/s / No Optical	
	<b>Power Supply</b>	450W PSU	
<b>Declared Noise Emissions</b>		<b>Sound Power (LWAd, bels)</b>	<b>Deskside Sound Pressure (LpAm, decibels)</b>

### System Technical Specifications

	<b>Idle</b>	3.44	26.3
	<b>Hard drive Operating</b> (random reads)	3.62	27.1
<b>System Configuration</b> <b>(High-end)</b>	<b>Processor Info</b>	Intel® Core™ i9-11900K 3.5GHz 8C CPU	
	<b>Memory Info</b>	64GB DDR4-3200 nECC (4x16GB) RAM	
	<b>Graphics Info</b>	NVIDIA® T1000 4GB	
	<b>Disks/Optical</b>	1x 2TB SATA 7200 rpm 6Gb/s / No Optical	
	<b>Power Supply</b>	450W PSU	
<b>Declared Noise Emissions</b>		<b>Sound Power</b> (LWAd, bels)	<b>Deskside Sound Pressure</b> (LpAm, decibels)
	<b>Idle</b>	3.41	25.5
	<b>Hard drive Operating</b> (random reads)	3.57	26.6

### System Technical Specifications

<b>Environmental Requirements</b>	<b>Temperature</b>	Operating: 5° to 35° C (40° to 95° F) Non-operating: -40° to 60° C (-40° to 140° F) Maximum rate of change: 10°C/hr
	<b>Humidity</b>	Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb
	<b>Maximum Altitude</b>	Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet) Non-operating: 12,192 m (40,000 feet) Maximum operating temperature is reduced as altitude increases. See Cooling for details.
	<b>Dynamic</b>	Shock Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g) square: 422 cm/s, 20g
	<b>Cooling</b>	Vibration Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g <sup>2</sup> /Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g <sup>2</sup> /Hz Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation, up to 3048 m (10,000 feet)

### Physical Security and Serviceability

<b>Access Panel</b>	Tool-less Includes system board and memory information
<b>Optical Drive</b>	Tool-less, except for Screw-In carrier
<b>Hard Drives</b>	Tool-less, except for internal/external and 2.5" bay
<b>Expansion Cards</b>	Tool-less
<b>Processor Socket</b>	Tool-less, except for the processor heatsink
<b>Blue User Touch Points</b>	Yes, on tool-less internal chassis mechanisms
<b>Color-coordinated Cables and Connectors</b>	Yes
<b>Memory</b>	Tool-less
<b>System Board</b>	Screw-In
<b>Padlock Support</b>	Yes (optional): Locks side cover and secures chassis from theft 0.22-in diameter padlock loop at rear of system
<b>Cable Lock Support</b>	Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft 3 mm x 7 mm slot at rear of system
<b>Universal Chassis Clamp Lock Support</b>	Yes (optional): Locks side cover and locks cables to chassis. Secures chassis from theft and allows multiple units to be chained together when used with optional cable Threaded feature at rear of system
<b>Solenoid Lock and Hood Sensor</b>	Yes (optional) The Solenoid Hood Lock eliminates the need for a physical key by making the chassis lockable through software and a password. You can also lock and unlock the chassis remotely over the network. The Sensor Kit detects when the access panel has been removed.
<b>Keyboard/Mouse/Video Cable Lock</b>	Yes, locks rear IO cables to prevent cable theft

### System Technical Specifications

<b>CPUs and Heatsinks</b>	A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be removed. CPU removal is tool-less
<b>Internal Speaker</b>	Yes
<b>Power Supply Fans</b>	70mm x 70mm x 25mm 4-wire PWM (non-serviceable)
<b>Access Panel Key Lock</b>	No
<b>Integrated Chassis Handles</b>	No
<b>Power Supply</b>	Requires T15 Torx or flat blade screwdriver
<b>PCI Card Retention</b>	Yes, rear (all), middle (none), front (none)

---

### Service, Support, and Warranty

On-site Warranty and Service<sup>1</sup>: Three-years, limited warranty and service offering delivers on-site, next business-day<sup>2</sup> service for parts and labor and includes free telephone support<sup>3</sup> 8am - 5pm. Global coverage<sup>2</sup> ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty.

**NOTE 1:** Terms and conditions may vary by country. Certain restrictions and exclusions apply.

**NOTE 2:** On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

**NOTE 3:** Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase.

To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at:

<http://www.hp.com/go/lookuptool>. Service levels and response times for HP Care Packs may vary depending on your geographic location.

---



### System Technical Specifications

#### BIOS

<b>BIOS 32-bit Services</b>	BIOS supports 64-bit Operating systems only.
<b>PCI 3.0 Support</b>	Full BIOS support for PCI Express through industry standard interfaces.
<b>ATAPI</b>	ATAPI Removable Media Device BIOS Specification Version 1.0.
<b>BBS</b>	BIOS Boot Specification v1.01.
<b>WMI Support</b>	WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM) and WBEM specifications.
<b>BIOS Boot Spec 1.01+</b>	Provides more control over how and from what devices the workstation will boot.
<b>BIOS Power On</b>	Users can define a specific date and time for the system to power on.
<b>ROM Based Computer Setup Utility (F10)</b>	Review and customize system configuration settings controlled by the BIOS.
<b>System/Emergency ROM Flash Recovery with Video</b>	Recovers system BIOS in corrupted Flash ROM.
<b>Replicated Setup</b>	Saves BIOS settings to USB flash device in human readable file (HpSetup.txt). BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed without entering Computer Configuration Utility (F10 Setup).
<b>SMBIOS</b>	System Management BIOS 3.2, for system management information.
<b>Boot Control</b>	Disables the ability to boot from removable media on supported devices.
<b>Memory Change Alert</b>	Alerts management console if memory is removed or changed.
<b>Thermal Alert</b>	Monitors the temperature state within the chassis. Three modes: <ul style="list-style-type: none"> <li>• NORMAL - normal temperature ranges.</li> <li>• ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown.</li> <li>• SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer without warning before hardware component damage occurs.</li> </ul>
<b>Remote ROM Flash</b>	Provides secure, fail-safe ROM image management from a central network console.
<b>ACPI (Advanced Configuration and Power Management Interface)</b>	Allows the system to enter and resume from low power modes (sleep states). Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system. Supports ACPI 6.0 for full compatibility with 64-bit operating systems.
<b>Ownership Tag</b>	A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.
<b>Remote Wakeup/Remote Shutdown</b>	System administrators can power on, restart, and power off a client computer from a remote location.
<b>Instantly Available PC (Suspend to RAM - ACPI sleep state S3)</b>	Allows for very low power consumption with quick resume time.
<b>Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server)</b>	Allows a new or existing system to boot over the network and download software, including the operating system.
<b>ROM revision levels</b>	Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW applications can use and report this information.
<b>System board revision level</b>	Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified.
<b>Start-up Diagnostics (Power-on Self-Test)</b>	Assesses system health at boot time with selectable levels of testing.
<b>Auto Setup when new hardware installed</b>	System automatically detects addition of new hardware.

### System Technical Specifications

<b>Keyboard-less Operation</b>	The system can be booted without a keyboard.
<b>Localized ROM Setup</b>	Common BIOS image supports System Configuration Utility (F10 Setup) menus in 14 languages with local keyboard mappings.
<b>Asset Tag</b>	The user or MIS to set a unique tag string in non-volatile memory.
<b>Per-slot Control</b>	Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually.
<b>Adaptive Cooling</b>	Control parameters are set according to detected hardware configuration for optimal acoustics.
<b>Pre-boot Diagnostics</b>	(Pre-video) critical errors are reported via beeps and blinks on the power LED.
<b>UEFI Specification</b>	
<b>Revision</b>	2.7
<b>ACPI</b>	Advanced Configuration and Power Management Interface, Version 6.0
<b>ATA (IDE)</b>	AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b
<b>CD Boot</b>	"El Torito" Bootable CD-ROM Format Specification Version 1.0
<b>EDD</b>	Enhanced Disk Drive Specification Version 1.1 BIOS Enhanced Disk Drive Specification Version 3.0
<b>EHCI</b>	Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0
<b>PCI</b>	PCI Local Bus Specification, Revision 2.3 PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7
<b>PCI Express</b>	PCI Express Base Specification, Revision 2.0 PCI Express Base Specification, Revision 3.0 PCI Express Base Specification, Revision 4.0
<b>PMM</b>	POST Memory Manager Specification, Version 1.01
<b>SATA</b>	Serial ATA Specification, Revision 1.0a Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0
<b>SPD</b>	PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B
<b>TPM</b>	Trusted Computing Group TPM Specification Version 2.0 (Infineon SLB 9670). Common Criteria EAL4+ certified. FIPS 140-2 Certification TCG TPM Certified products list: <a href="http://www.trustedcomputinggroup.org/certification/tpm-certified-products/">http://www.trustedcomputinggroup.org/certification/tpm-certified-products/</a>
<b>UHCI</b>	Universal Host Controller Interface Design Guide, Revision 1.1
<b>USB</b>	Universal Serial Bus Revision 1.1 Specification  Universal Serial Bus Revision 2.0 Specification  Universal Serial Bus Revision 3.1 Specification
<b>SMBIOS</b>	System Management BIOS Reference Specification, Version 3.2  External BIOS simulator found at: <a href="http://csrmsl.itcs.hp.com/">http://csrmsl.itcs.hp.com/</a>

### Social and Environmental Responsibility

<b>Eco-Label Certifications &amp; Declarations</b>	<p>This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:</p> <ul style="list-style-type: none"> <li>• IT ECO declaration</li> <li>• US ENERGY STAR®</li> <li>• US Federal Energy Management Program (FEMP)</li> <li>• EPEAT<sup>®</sup> Gold registered in the United States. See <a href="http://www.epeat.net">http://www.epeat.net</a> for registration status in your country.</li> <li>• TCO Certified configurations available</li> </ul>
--	--

### System Technical Specifications

- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label\*

#### Sustainable Impact Specifications

- 45% post-consumer recycled plastic
- External Power Supply 90% Efficiency
- Low halogen
- Outside Box and corrugated cushions are 100% sustainably sourced and recyclable
- Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable

#### System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a “Typically Configured Notebook”.

#### Energy Consumption (in accordance with US ENERGY STAR® test method)

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Sort idle)	40.30 W	40.88 W	38.25 W
Normal Operation (Long idle)	38.70 W	38.89 W	38.7 W
Sleep	2.56 W	2.77 W	2.75 W
Off	0.81 W	0.81 W	0.81 W

#### Note:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

#### Heat Dissipation\*

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	140 BTU/hr	140 BTU/hr	140 BTU/hr
Normal Operation (Long idle)	132 BTU/hr	135 BTU/hr	132 BTU/hr
Sleep	9 BTU/hr	9 BTU/hr	9 BTU/hr
Off	3 BTU/hr	3 BTU/hr	3 BTU/hr

\*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

#### Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

	Sound Power (L <sub>WAd</sub> , bels)	Sound Pressure (L <sub>pAm</sub> , decibels)
Typically Configured – Idle	3.42	24.5
Fixed Disk – Random writes	3.59	25.4
Optical Drive – Sequential reads	4.15	32.7

#### Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the

### System Technical Specifications

Spare parts are available throughout the warranty period and or for up to “5” years after the end of production.

#### Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level, see [www.epeat.net](http://www.epeat.net)
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 94.2% recycle-able when properly disposed of at end of life.

#### Packaging Materials

<b>External:</b>	PAPER/Corrugated	1158 g
<b>Internal:</b>	PAPER/Molded pulp	390 g
	PLASTIC/Polyethylene low density	28 g

The plastic packaging material contains at least 80% recycled content.

The corrugated paper packaging materials contains at least 100% recycled content.

#### RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see [Error! Hyperlink reference not valid. HP RoHS position statement.](#)

#### Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

[http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen\\_specifications.html](http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html)):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde

### System Technical Specifications

- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBEBs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

#### Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

#### End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <http://www.hp.com/go/reuse-recycle> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: <http://www.hp.com/go/recyclers>. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

#### HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

<http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html>

Eco-label certifications

<http://www8.hp.com/us/en/hp-information/environment/ecolabels.html>

ISO 14001 certificates:

<http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842>

and

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf>

#### Footnotes

- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.

### System Technical Specifications

- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials.
- Plastic cushions are made from >90% recycled plastic.

Name	Cores	Clock Speed (GHz)	Intel® Turbo Boost Technology <sup>3</sup>	Cache (MB)	Memory Speed (MT/s)	Hyper-Threading	Integrated Graphics	Featuring Intel® vPro® Technology <sup>4</sup>	16GB Intel® Optane™ memory <sup>2</sup>	TDP (W)
Intel® Core™ i9 11900K Processor	8	3.5	5.2	16	3200	Y	Intel® UHD Graphics 750	Y	Y	125
Intel® Core™ i9 11900F Processor	8	2.5	5.1	16	3200	Y	N/A	N/A	Y	65
Intel® Core™ i9 11900 Processor	8	2.5	5.1	16	3200	Y	Intel® UHD Graphics 750	Y	Y	65
Intel® Core™ i7 11700K Processor	8	3.6	5	16	3200	Y	Intel® UHD Graphics 750	Y	Y	125
Intel® Core™ i7 11700 processor	8	2.5	4.9	16	3200	Y	Intel® UHD Graphics 750	Y	Y	65
Intel® Core™ i5 11600K processor	6	3.9	4.9	12	3200	Y	Intel® UHD Graphics 750	Y	Y	125
Intel® Core™ i5 11600 processor	6	2.8	4.8	12	3200	Y	Intel® UHD Graphics 750	Y	Y	65
Intel® Core™ i5 11500 processor	6	2.7	4.6	12	3200	Y	Intel® UHD Graphics 750	Y	Y	65
Intel® Core™ i5 11400F processor	6	2.6	4.4	12	3200	Y	N/A	N/A	Y	65
Intel® Core™ i5 11400 processor	6	2.6	4.4	12	3200	Y	Intel® UHD Graphics 730	N/A	Y	65
Intel® Xeon® W-1390P processor	8	3.5	5.2	16	3200	Y	Intel® UHD Graphics P750	Y	Y	125
Intel® Xeon® W-1390 processor	8	2.8	5.1	16	3200	Y	Intel® UHD Graphics P750	Y	Y	80
Intel® Xeon® W-1370P processor	8	3.6	5.2	16	3200	Y	Intel® UHD Graphics P750	Y	Y	125
Intel® Xeon® W-1370 processor	8	2.9	5.1	16	3200	Y	Intel® UHD Graphics P750	Y	Y	80
Intel® Xeon® W-1350P processor	6	4	5.1	12	3200	Y	Intel® UHD Graphics P750	Y	Y	125
Intel® Xeon® W-1350 processor	6	3.3	5	12	3200	Y	Intel® UHD Graphics P750	Y	Y	80

1. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

### System Technical Specifications

2. Intel® Optane™ memory is sold separately. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Available for HP commercial desktops and notebooks and for select HP workstations (HP Z240 Tower/SFF, Z2 Mini, ZBook Studio, 15 and 17 G5) and requires a SATA HDD, 7th Gen or higher Intel® Core™ processor or Intel® Xeon® processor E3-1200 V6 product family or higher, BIOS version with Intel® Optane™ supported, M.2 type 2280-S1-B-M connector on a PCH Remapped PCIe Controller and Lanes in a x2 or x4 configuration with B-M keys that meet NVMe™ Spec 1.1, and an Intel® Rapid Storage Technology (Intel® RST) 15.5 driver.

3. The specifications shown in the Intel® Turbo Boost Technology column represent the maximum turbo frequency with one core active. Turbo boost stepping occurs in 100MHz increments. Processors that do not have turbo functionality are denoted as N/A. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See <http://www.intel.com/technology/turboboost> for more information

4. For full Intel® vPro® functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See <http://intel.com/vpro>

### Technical Specifications - Hard Drives

#### SATA Hard Drives for HP Workstations

#### 500GB SATA 7200 rpm 6Gb/s 3.5" HDD

<b>Capacity</b>	500GB	
<b>Height</b>	1 in; 2.54 cm	
<b>Width</b>		<b>Media Diameter</b> 3.5 in; 8.9 cm
		<b>Physical Size</b> 4 in; 10.17 cm
<b>Interface</b>	Serial ATA (6.0Gb/s)	
<b>Synchronous Transfer Rate (Maximum)</b>	Up to 600MB/s *	
<b>Buffer</b>	32MB	
<b>Seek Time (typical reads, includes controller overhead, including settling)</b>		<b>Single Track</b> 2 ms *
		<b>Average</b> 11 ms*
		<b>Full Stroke</b> 21 ms *
<b>Rotational Speed</b>	7,200 rpm	
<b>Logical Blocks</b>	976,773,168	
<b>Operating Temperature</b>	41° to 131° F (5° to 55° C)	

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 1TB SATA 7200 rpm 6Gb/s 3.5" HDD

<b>Capacity</b>	1 Terabyte (1000 GB)	
<b>Height</b>	1 in; 2.54 cm	
<b>Width</b>		<b>Media Diameter</b> 3.5 in; 8.9 cm
		<b>Physical Size</b> 4 in; 10.17 cm
<b>Interface</b>	Serial ATA (6.0Gb/s), NCQ enabled	
<b>Synchronous Transfer Rate (Maximum)</b>	Up to 600 MB/s *	
<b>Buffer</b>	64MB	
<b>Seek Time (typical reads, includes controller overhead, including settling)</b>		<b>Single Track</b> 2 ms *
		<b>Average</b> 11 ms *
		<b>Full Stroke</b> 21 ms *
<b>Rotational Speed</b>	7,200 rpm	
<b>Logical Blocks</b>	1,953,525,168	
<b>Operating Temperature</b>	41° to 131° F (5° to 55° C)	

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 2TB SATA 7200 rpm 6Gb/s 3.5" HDD

<b>Capacity</b>	2TB	
<b>Height</b>	1 in; 2.54 cm	
<b>Width</b>		<b>Media Diameter</b> 3.5 in; 8.9 cm
		<b>Physical Size</b> 4 in; 10.17 cm
<b>Interface</b>	Serial ATA (6.0 Gb/s), NCQ Enabled	



### Technical Specifications - Hard Drives

<b>Synchronous Transfer Rate (Maximum)</b>	Up to 600MB/s *	
<b>Buffer</b>	64MB	
<b>Seek Time (typical reads, includes controller overhead, including settling)</b>	<b>Single Track</b>	2.0 ms *
	<b>Average</b>	11 ms *
	<b>Full Stroke</b>	21 ms *
<b>Rotational Speed</b>	7,200 rpm	
<b>Logical Blocks</b>	3,907,029,168	
<b>Operating Temperature</b>	41° to 131° F (5° to 55° C)	

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 1TB SATA 7200 rpm 6GB/s 3.5" HDD (Enterprise Class)

<b>Capacity</b>	1TB	
<b>Protocol</b>	SATA	
<b>Form Factor</b>	3.5"	
<b>Controller</b>	AHCI	
<b>Reliability (MTBF)</b>	2.0M hours	
<b>Rated Power On Hours</b>	8760/yr	
<b>Annualized Failure Rate (based on Rated POH)</b>	<0.62%	
<b>Rated for 24/7/365 Operation</b>	YES	
<b>Physical Size (Height)</b>	1 in; 2.54 cm	
<b>Physical Size (Width)</b>	4 in; 10.17 cm	
<b>Media Diameter</b>	3.5 in; 8.9 cm	
<b>Interface</b>	Serial ATA (6Gb/s), NCQ enabled	
<b>Synchronous Transfer Rate (Maximum)</b>	Up to 600MB/s*	
<b>Buffer</b>	128MB	
<b>Seek Time (typical reads, includes controller overhead, including settling)</b>	<b>Single Track</b>	0.32ms*
	<b>Average</b>	7.45ms*
	<b>Full Stroke</b>	14.2ms*
<b>Operating Temperature</b>	41° to 140° F (5° to 60° C)	
<b>Performance</b>	<b>Sequential Read</b>	up to 226MB/s*
	<b>Sequential Write</b>	up to 226MB/s*
<b>Enterprise Class Features</b>	High Reliability	

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

### Technical Specifications - Hard Drives

**2TB SATA 7200 rpm  
6GB/s 3.5" HDD  
(Enterprise Class)**

<b>Capacity</b>	2TB
<b>Protocol</b>	SATA
<b>Form Factor</b>	3.5"
<b>Controller</b>	AHCI
<b>Reliability (MTBF)</b>	2.0M hours
<b>Rated Power On Hours</b>	8760/yr
<b>Annualized Failure Rate (based on Rated POH)</b>	<0.62%
<b>Physical Size (Height)</b>	1 in; 2.54 cm
<b>Physical Size (Width)</b>	4 in; 10.17 cm
<b>Media Diameter</b>	3.5 in; 8.9 cm
<b>Interface</b>	Serial ATA (6Gb/s), NCQ enabled
<b>Synchronous Transfer Rate (Maximum)</b>	Up to 600MB/s*
<b>Buffer</b>	128MB
<b>Seek Time (typical reads, Single Track includes controller overhead, including settling)</b>	0.7ms*
	<b>Average</b> 8.5ms*
	<b>Full Stroke</b> 15.7ms*
<b>Operating Temperature</b>	41° to 131° F (5° to 55° C)
<b>Performance</b>	<b>Sequential Read</b> up to 226MB/s*
	<b>Sequential Write</b> up to 226MB/s*

**Enterprise Class Features** High Reliability

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

**4TB SATA 7200 rpm  
6Gb/s 3.5" HDD  
(Enterprise Class)**

<b>Capacity</b>	4TB
<b>Protocol</b>	SATA
<b>Form Factor</b>	3.5"
<b>Controller</b>	AHCI
<b>Reliability (MTBF)</b>	2.0M hours
<b>Rated Power On Hours</b>	8760/yr
<b>Annualized Failure Rate (based on Rated POH)</b>	<0.62%
<b>Rated for 24/7/365 Operation</b>	YES
<b>Physical Size (Height)</b>	1 in; 2.54 cm
<b>Physical Size (Width)</b>	4 in; 10.17 cm
<b>Media Diameter</b>	3.5 in; 8.9 cm
<b>Interface</b>	Serial ATA (6Gb/s), NCQ enabled
<b>Synchronous Transfer Rate (Maximum)</b>	Up to 600MB/s*

### Technical Specifications - Hard Drives

<b>Buffer</b>	128MB
<b>Seek Time</b> (typical reads, includes controller overhead, including settling)	<b>Single Track</b> 0.7ms* <b>Average</b> 8.5ms* <b>Full Stroke</b> 15.7ms*
<b>Operating Temperature</b>	41° to 131° F (5° to 55° C)
<b>Performance</b>	<b>Sequential Read</b> up to 226MB/s* <b>Sequential Write</b> up to 226MB/s*
<b>Enterprise Class Features</b>	High Reliability

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 8TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

<b>Capacity</b>	8TB
<b>Protocol</b>	SATA
<b>Form Factor</b>	3.5"
<b>Controller</b>	AHCI
<b>Reliability (MTBF)</b>	2.0M hours
<b>Physical Size (Width)</b>	4 in; 10.17 cm
<b>Media Diameter</b>	3.5 in; 8.9 cm
<b>Interface</b>	Serial ATA (6Gb/s), NCQ enabled
<b>Synchronous Transfer Rate (Maximum)</b>	Up to 600MB/s*
<b>Buffer</b>	256MB
<b>Seek Time</b> (typical reads, includes controller overhead, including settling)	<b>Single Track</b> 0.7ms* <b>Average</b> 8.5ms* <b>Full Stroke</b> 15.7ms*
<b>Operating Temperature</b>	41° to 140° F (5° to 60°C)
<b>Performance</b>	<b>Sequential Read</b> up to 226MB/s* <b>Sequential Write</b> up to 226MB/s*
<b>Enterprise Class Features</b>	High Reliability

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 500GB SATA 7.2K SED SFF HDD

<b>Capacity</b>	500GB
<b>Protocol</b>	SATA
<b>Form Factor</b>	2.5"
<b>Height</b>	0.275 in; 0.7 cm
<b>Physical Size (Width)</b>	2.75 in; 6.99 cm
<b>Media Diameter</b>	2.5 in; 6.36 cm
<b>Interface</b>	Serial ATA (6Gb/s), NCQ enabled
<b>Synchronous Transfer Rate (Maximum)</b>	Up to 600MB/s*

### Technical Specifications - Hard Drives

<b>Buffer</b>	64MB
<b>Seek Time</b> (typical reads, includes controller overhead, including settling)	<b>Single Track</b> 1ms* <b>Average</b> 4.2ms* <b>Full Stroke</b> 25ms (Typical)*
<b>Operating Temperature</b>	32° to 131° F (0° to 60° C)
<b>Self-Encrypting Drive Support</b>	Yes

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### HP Z Turbo Drv PCIe-4X4 256GB TLC PCIe SSD (Z2G8)

<b>Capacity</b>	256GB
<b>Protocol</b>	PCIe
<b>Form Factor</b>	M.2 in native Slot on motherboard
<b>Controller</b>	NVMe
<b>NAND Type</b>	3D TLC
<b>Endurance</b>	75TBW (TB Written)
<b>Reliability</b>	1.5M Hours
<b>Interface</b>	PCI Express 4.0 x4 electrical
<b>Operating Temperature</b>	32° to 178° F (0° to 81° C)
<b>Performance</b>	<b>Sequential Read</b> 5500MB/s* <b>Sequential Write</b> 2300MB/s* <b>Random Read</b> 400K IOPS* <b>Random Write</b> 400K IOPS*

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### HP Z Turbo Drv PCIe-4X4 512GB TLC PCIe SSD (Z2G8)

<b>Capacity</b>	512GB
<b>Protocol</b>	PCIe
<b>Form Factor</b>	M.2 in native Slot on motherboard
<b>Controller</b>	NVMe
<b>NAND Type</b>	3D TLC
<b>Endurance</b>	150TBW (TB Written)
<b>Reliability</b>	1.5M Hours
<b>Interface</b>	PCI Express 4.0 x4 electrical
<b>Operating Temperature</b>	32° to 178° F (0° to 81° C)
<b>Performance</b>	<b>Sequential Read</b> 6400MB/s* <b>Sequential Write</b> 3400MB/s* <b>Random Read</b> 600K IOPS* <b>Random Write</b> 600K IOPS*

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

### Technical Specifications - Hard Drives

<b>HP Z Turbo Drv PCIe-4X4 1TB TLC PCIe SSD (Z2G8)</b>	<b>Capacity</b>	1TB		
	<b>Protocol</b>	PCIe		
	<b>Form Factor</b>	M.2 in native Slot on motherboard		
	<b>Controller</b>	NVMe		
	<b>NAND Type</b>	3D TLC		
	<b>Endurance</b>	300TBW (TB Written)		
	<b>Reliability</b>	1.5M Hours		
	<b>Interface</b>	PCI Express 4.0 x4 electrical		
	<b>Operating Temperature</b>	32° to 178° F (0° to 81° C)		
	<b>Performance</b>	<b>Sequential Read</b>	6500MB/s*	
		<b>Sequential Write</b>	5000MB/s*	
		<b>Random Read</b>	800K IOPS*	
		<b>Random Write</b>	800K IOPS*	

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

<b>HP Z Turbo Drv PCIe-4X4 2TB TLC PCIe SSD (Z2G8)</b>	<b>Capacity</b>	2TB		
	<b>Protocol</b>	PCIe		
	<b>Form Factor</b>	M.2 in native Slot on motherboard		
	<b>Controller</b>	NVMe		
	<b>NAND Type</b>	3D TLC		
	<b>Endurance</b>	600TBW (TB Written)		
	<b>Reliability</b>	1.5M Hours		
	<b>Interface</b>	PCI Express 4.0 x4 electrical		
	<b>Operating Temperature</b>	32° to 178° F (0° to 81° C)		
	<b>Performance</b>	<b>Sequential Read</b>	6500MB/s*	
		<b>Sequential Write</b>	5000MB/s*	
		<b>Random Read</b>	800K IOPS*	
		<b>Random Write</b>	800K IOPS*	

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

<b>HP Z Turbo Drv 256GB TLC PCIe SED OPAL2 (Z2G5)</b>	<b>Capacity</b>	256GB	
	<b>Protocol</b>	PCIe	
	<b>Form Factor</b>	M.2 in native Slot on motherboard	
	<b>Controller</b>	NVMe	
	<b>NAND Type</b>	3D TLC	
	<b>Endurance</b>	75TBW (TB Written)	
	<b>Reliability</b>	1.5M Hours	
	<b>Interface</b>	PCI Express 4.0 x4 electrical	
	<b>Operating Temperature</b>	32° to 178° F (0° to 81° C)	

### Technical Specifications - Hard Drives

<b>Performance</b>	<b>Sequential Read</b>	5500MB/s*
	<b>Sequential Write</b>	2300MB/s*
	<b>Random Read</b>	400K IOPS*
	<b>Random Write</b>	400K IOPS*
	<b>Self-Encrypting Drive Support</b>	OPAL2

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### HP Z Turbo Drv 512GB TLC PCIe SED OPAL2 (Z2G5)

<b>Capacity</b>	512GB	
<b>Protocol</b>	PCIe	
<b>Form Factor</b>	M.2 in native Slot on motherboard	
<b>Controller</b>	NVMe	
<b>NAND Type</b>	3D TLC	
<b>Endurance</b>	150TBW (TB Written)	
<b>Reliability</b>	1.5M Hours	
<b>Interface</b>	PCI Express 4.0 x4 electrical	
<b>Operating Temperature</b>	32° to 178° F (0° to 81° C)	
<b>Performance</b>	<b>Sequential Read</b>	6400MB/s*
	<b>Sequential Write</b>	3400MB/s*
	<b>Random Read</b>	600K IOPS*
	<b>Random Write</b>	600K IOPS*
	<b>Self-Encrypting Drive Support</b>	OPAL2

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### HP Z Turbo Drv 1TB TLC PCIe SED OPAL2 (Z2G5)

<b>Capacity</b>	1TB	
<b>Protocol</b>	PCIe	
<b>Form Factor</b>	M.2 in native Slot on motherboard	
<b>Controller</b>	NVMe	
<b>NAND Type</b>	3D TLC	
<b>Endurance</b>	300TBW (TB Written)	
<b>Reliability</b>	1.5M Hours	
<b>Interface</b>	PCI Express 4.0 x4 electrical	
<b>Operating Temperature</b>	32° to 178° F (0° to 81° C)	
<b>Performance</b>	<b>Sequential Read</b>	6500MB/s*
	<b>Sequential Write</b>	5000MB/s*
	<b>Random Read</b>	800K IOPS*
	<b>Random Write</b>	800K IOPS*
	<b>Self-Encrypting Drive Support</b>	OPAL2

### Technical Specifications - Hard Drives

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

<b>HP Z Turbo Drv 2TB TLC PCIe SED OPAL2 (Z2G5)</b>	<b>Capacity</b>	2TB	
	<b>Protocol</b>	PCIe	
	<b>Form Factor</b>	M.2 in native Slot on motherboard	
	<b>Controller</b>	NVMe	
	<b>NAND Type</b>	3D TLC	
	<b>Endurance</b>	600TBW (TB Written)	
	<b>Interface</b>	PCI Express 4.0 x4 electrical	
	<b>Operating Temperature</b>	32° to 178° F (0° to 81° C)	
	<b>Performance</b>	<b>Sequential Read</b>	6500MB/s*
		<b>Sequential Write</b>	5000MB/s*
		<b>Random Read</b>	800K IOPS*
		<b>Random Write</b>	800K IOPS*
<b>Self-Encrypting Drive Support</b>	OPAL2		

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

<b>256GB M.2 2280 PCIE TLC SSD (Z2G8)</b>	<b>Capacity</b>	256GB	
	<b>Protocol</b>	PCIe	
	<b>Form Factor</b>	M.2 in native Slot on motherboard	
	<b>Controller</b>	NVMe	
	<b>NAND Type</b>	3D TLC	
	<b>Endurance</b>	200TBW (TB Written)	
	<b>Reliability</b>	1.5M Hours	
	<b>Interface</b>	PCI Express 3.0 x4 electrical	
	<b>Operating Temperature</b>	32° to 158° F (0° to 70° C)	
	<b>Performance</b>	<b>Sequential Read</b>	3100MB/s*
		<b>Sequential Write</b>	1400MB/s*
		<b>Random Read</b>	200K IOPS*
<b>Random Write</b>		400K IOPS*	

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

<b>512GB M.2 2280 PCIE TLC SSD (Z2G8)</b>	<b>Capacity</b>	512GB	
	<b>Protocol</b>	PCIe	
	<b>Form Factor</b>	M.2 in native Slot on motherboard	
	<b>Controller</b>	NVMe	
	<b>NAND Type</b>	3D TLC	

### Technical Specifications - Hard Drives

<b>Endurance</b>	300TBW (TB Written)	
<b>Reliability</b>	1.5M Hours	
<b>Interface</b>	PCI Express 3.0 x4 electrical	
<b>Operating Temperature</b>	32° to 158° F (0° to 70° C)	
<b>Performance</b>	<b>Sequential Read</b>	3400MB/s*
	<b>Sequential Write</b>	2500MB/s*
	<b>Random Read</b>	380K IOPS*
	<b>Random Write</b>	430K IOPS*

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 1TB M.2 2280 PCIe TLC SSD (Z2G8)

<b>Capacity</b>	1TB	
<b>Protocol</b>	PCIe	
<b>Form Factor</b>	M.2 in native Slot on motherboard	
<b>Controller</b>	NVMe	
<b>NAND Type</b>	3D TLC	
<b>Endurance</b>	400TBW (TB Written)	
<b>Reliability</b>	1.5M Hours	
<b>Interface</b>	PCI Express 4.0 x4 electrical	
<b>Operating Temperature</b>	32° to 158° F (0° to 70° C)	
<b>Performance</b>	<b>Sequential Read</b>	3400MB/s*
	<b>Sequential Write</b>	2500MB/s*
	<b>Random Read</b>	500K IOPS*
	<b>Random Write</b>	440K IOPS*

\*Actual performance may vary.

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 2TB M.2 2280 PCIe TLC SSD (Z2G8)

<b>Capacity</b>	2TB	
<b>Protocol</b>	PCIe	
<b>Form Factor</b>	M.2 in native Slot on motherboard	
<b>Controller</b>	NVMe	
<b>NAND Type</b>	3D TLC	
<b>Endurance</b>	600TBW (TB Written)	
<b>Reliability</b>	1.5M Hours	
<b>Interface</b>	PCI Express 3.0 x4 electrical	
<b>Operating Temperature</b>	32° to 158° F (0° to 70° C)	
<b>Performance</b>	<b>Sequential Read</b>	3400MB/s*
	<b>Sequential Write</b>	2500MB/s*
	<b>Random Read</b>	430K IOPS*
	<b>Random Write</b>	500K IOPS*

\*Actual performance may vary.



### Technical Specifications - Hard Drives

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

### Technical Specifications - Graphics

<b>Integrated Intel® UHD Graphics (Z2 G8)</b>	<b>Form Factor</b>	Integrated in select Intel® Xeon®, Intel® Core™ i9/ i7, and Intel® Core™ i5 processors.
		Check specific platform specifications for selections.
	<b>Graphics Controller</b>	Intel® UHD Graphics
	<b>Memory</b>	Unified Memory Architecture (UMA) frame buffer. Graphics memory is shared with system memory. Size selectable between 64 MB to 1024 MB via BIOS setting. Default size is 64 MB. Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (Intel® DVMT 5.0), to provide an optimal balance between graphics and system memory use.
	<b>Connectors</b>	Check system platform specifications where Intel® UHD Graphics are available.
	<b>Maximum Resolution</b>	Display Port: 4096 x 2160 (5120x3200 could be achieved if output from FlexIO ports - DP/USB-C/TBT) HDMI: 4096 x 2160 DVI: 1920x1200 VGA: 2048x1536
	<b>Shading Architecture</b>	Shader Model 6 compiler support
	<b>Supported Graphics APIs</b>	OpenGL 4.6 DirectX 12
<b>Available Graphics Drivers</b>	Windows 11 Windows 10	

**NOTE:** For HDMI, DVI and VGA outputs, separate adapters may be required.

<b>AMD Radeon™ Pro WX 3200 4GB Graphics</b>	<b>Form Factor</b>	Low-Profile Single Slot (2.75 "H x 6.6" L)
	<b>Graphics Controller</b>	Radeon™ Pro WX 3200 Power: 56 Watts Cooling Solution: Active fan heatsink
	<b>Memory</b>	4GB GDDR5 memory
	<b>Maximum Resolution</b>	DisplayPort™ 1.4: - up to 4x 4096 x 2160 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST)
	<b>Shading Architecture</b>	Full Microsoft DirectX 12 Shader Model 5.1
	<b>Display Outputs</b>	4 mDP (Mini DisplayPort™) 1.4 Connectors
	<b>Shading Architecture</b>	Full Microsoft DirectX 12 Shader Model 5.1
	<b>Supported Graphics APIs</b>	DirectX® 12 OpenGL® 4.5 OpenCL™ 2.0 Vulkan™ 1.0
	<b>Available Graphics Drivers</b>	Windows 11 Windows 10 (Windows® 7 64-bit available from AMD) Linux® 64-bit (selected Enterprise distributions)

### Technical Specifications - Graphics

HP qualified drivers may be preloaded or available from the HP support Web site:  
<http://welcome.hp.com/country/us/en/support.html>

#### Notes

1. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.
2. WX 3200 only has mini-DisplayPort™ (mDP) video ports. Two mDP-to-DP Adapters are included in the WX 3200 AMO kit. If more mDP-to-DP Adapters are needed, Adapters can be ordered separately:
  - 2MY05AA HP Single miniDP-to-DP Adapter Cable

#### NVIDIA® T1000 4GB Graphics

##### Form Factor Graphics Controller

Low-Profile Single Slot (6.13" Length )  
 NVIDIA® T1000 4GB Graphics  
 Power: 50 Watts  
 Cooling: Active Fan Heatsink

##### Memory Maximum Resolution

4GB GDDR6 memory  
 DisplayPort™ 1.4a:  
 - up to 4x 5210 x 3200 x 24 bpp @ 60Hz, uncompressed  
 - 7680 x 4320 x 36 bpp @ 60Hz, compressed  
 - supports Multi-Stream Transport (MST)

##### Display Output Shading Architecture Supported Graphics APIs

4 mDP (Mini DisplayPort™) 1.4 Connectors  
 Shader Model 5.1  
 DirectX®12  
 OpenGL® 4.6  
 OpenCL™ 1.2  
 Vulkan™ 1.2

##### Available Graphics Drivers

Windows 11  
 Windows 10  
 Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support Web site:  
<http://welcome.hp.com/country/us/en/support.html>

#### Notes

#### NVIDIA® Quadro® RTX 3000 6GB Graphics

##### Form Factor Graphics Controller

Low-Profile Dual Slot (6.6" Length )  
 NVIDIA Quadro RTX 3000 6GB Graphics  
 Power: 60 Watts  
 Cooling: Active Fan Heatsink

##### Bus Type Memory Connectors

PCI Express 3.0 x16  
 6GB GDDR6 memory  
 4x Mini DisplayPort™1.4 – HDR ready connectors with HBR3 and MST support.

### Technical Specifications - Graphics

<b>Maximum Resolution</b>	DisplayPort™1.4: - up to 4x 5120 x 2880 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST)
<b>Display Output</b>	4x Mini DisplayPort™1.4 – HDR ready connectors
<b>GPU Architecture</b>	Turing
<b>Shading Architecture</b>	Shader Model 6.5
<b>Supported Graphics APIs</b>	DirectX®12 OpenGL® 4.6 OpenCL™ 2.1 Vulkan™ 1.2
<b>Available Graphics Drivers</b>	Windows 11 Windows 10 Linux® 64-bit (selected Enterprise distributions)
	HP qualified drivers may be preloaded or available from the HP support Web site: <a href="http://welcome.hp.com/country/us/en/support.html">http://welcome.hp.com/country/us/en/support.html</a>

#### Notes

<b>NVIDIA® Quadro® P400 2GB Graphics</b>	<b>Form Factor</b>	Single Slot, Low Profile (2.713" H x 5.7" L)
	<b>Graphics Controller</b>	NVIDIA® Quadro® P400 Graphics Card Max Power: 30 Watts Cooling Solution: Active fan heatsink
	<b>Bus Type</b>	PCI Express 3.0 x16
	<b>Memory</b>	Size: 2GB DDR5
	<b>Maximum Resolution</b>	DisplayPort™ 1.4: - up to 3x 5120 x 2880 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST)
	<b>Display Output</b>	3 mDP (Mini DisplayPort™) 1.4 Connectors
	<b>Shading Architecture</b>	Full Microsoft DirectX 12 Shader Model 5.1
	<b>Supported Graphics APIs</b>	OpenGL 4.5 DirectX 12 Vulkan 1.0 API support includes: CUDA, OpenCL 1.x
	<b>Available Graphics Drivers</b>	Windows 11 Windows 10 Linux® 64-bit (selected Enterprise distributions)
	<b>Notes</b>	HP qualified drivers may be preloaded or available from the HP support Web site: <a href="http://welcome.hp.com/country/us/en/support.html">http://welcome.hp.com/country/us/en/support.html</a> *P400 only have mini-DisplayPort™ (mDP) video ports. <b>Note</b> : AMO kits for P400 Adapters <ul style="list-style-type: none"> <li>• Two mDP-to-DP Adapters are included in the P400 AMO kits.</li> <li>• If more mDP-to-DP Adapters are needed, Adapters can be ordered separately: <ul style="list-style-type: none"> <li>- 2MY05AA - HP Single miniDP-to-DP Adapter Cable</li> </ul> </li> </ul>

### Technical Specifications - Graphics

#### NVIDIA® T400 2GB Graphics

<b>Form Factor</b>	Dimensions: 2.713" H x 6.137" L Single Slot, Low Profile Weight: 124g
<b>Graphics Controller</b>	NVIDIA® T400 Graphics Card GPU: 384 CUDA cores Power: 30 Watts Cooling: Active
<b>Bus Type</b>	PCI Express 3.0 x16
<b>Memory</b>	Size: 2 GB GDDR6 Memory Interface: 64-bit Memory Bandwidth: 80 GB/s
<b>Connectors</b>	3x mDP
<b>Maximum Resolution</b>	3x 5120 x 2880 x 24 bpp @ 60Hz
<b>Supported Graphics APIs</b>	OpenGL 4.5 DirectX 12 Vulkan 1.0 API support includes: CUDA, OpenCL 1.x
<b>Available Graphics Drivers</b>	Windows 11 Windows 10 Linux
	HP qualified drivers may be preloaded or available from the HP support Web site: <a href="http://welcome.hp.com/country/us/en/support.html">http://welcome.hp.com/country/us/en/support.html</a>

#### NVIDIA® T600 4GB Graphics

<b>Form Factor</b>	Dimensions: 2.713" H x 5.7" L Single Slot, Low Profile
<b>Graphics Controller</b>	NVIDIA® T600 Graphics Card GPU: 640 CUDA cores Power: 40 Watts Cooling: Active
<b>Bus Type</b>	PCI Express 3.0 x16
<b>Memory</b>	Size: 4 GB GDDR6 Memory Interface: 128-bit Memory Bandwidth: 160 GB/s
<b>Connectors</b>	4x mDP
<b>Maximum Resolution</b>	7680 x 4320 @ 60Hz
<b>Display Output</b>	4x mDP
<b>Supported Graphics APIs</b>	OpenGL 4.5 DirectX 12 Vulkan 1.0 API support includes: CUDA C, CUDA C++, DirectCompute , OpenCL
<b>Available Graphics Drivers</b>	Windows 11 Windows 10

### Technical Specifications - Graphics

Linux

HP qualified drivers may be preloaded or available from the HP support Web site:

<http://welcome.hp.com/country/us/en/support.html>

### Technical Specifications - Optical and Removable Storage

#### HP 9.5mm Slim DVD Writer

<b>Description</b>	9.5mm height, tray-load
<b>Mounting Orientation</b>	Either horizontal or vertical
<b>Interface Type</b>	SATA/ATAPI
<b>Dimensions (WxHxD)</b>	128 x 9.5 x 127mm
<b>Supported Media Types</b>	DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW
<b>Disc Capacity</b>	<b>DVD-ROM</b> 8.5 GB DL or 4.7 GB standard
<b>Access Times</b>	<b>Full Stroke DVD</b> < 200ms (seek) <b>Full Stroke CD</b> < 200ms (seek)
<b>Maximum Data Transfer Rates</b>	<b>CD ROM Read</b> CD-ROM, CD-R Up to 24X CD-RW Up to 24X  <b>DVD ROM Read</b> DVD+RW Up to 8X DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X
<b>Power</b>	<b>Source</b> SATA DC power receptacle <b>DC Power Requirements</b> 5 VDC ± 5%-100 mV ripple p-p <b>DC Current</b> 5 VDC – < 800 mA typical, < 1600 mA maximum
<b>Operating Environmental (all conditions non-condensing)</b>	<b>Temperature</b> 41° to 122° F (5° to 50° C) <b>Relative Humidity</b> 10% to 80% <b>Maximum Wet Bulb Temperature</b> 84° F (29° C)
<b>Operating Systems Supported</b>	Windows 11, Windows 10, Windows 7 Professional 32-bit and 64-bit, Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows 2000, Windows XP Professional or Windows XP Home 32*. Linux®
<b>Kit Contents</b>	No driver is required for this device. Native support is provided by the operating system. HP SATA DVD Writer drive, installation guide.
<b>Approvals</b>	USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport Specification Rev. 1.0, Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE, BSMI, C-Tick, VCCI, MIC, cUL, TUVT

**NOTE:** Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than

### Technical Specifications - Optical and Removable Storage

single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

<b>HP 9.5mm Slim DVD-ROM Drive</b>	<b>Description</b>	9.5mm height, tray-load	
	<b>Mounting Orientation</b>	Either horizontal or vertical	
	<b>Interface Type</b>	SATA / ATAPI	
	<b>Dimensions (WxHxD)</b>	128 x 9.5 x 127mm	
	<b>Disc Capacity</b>	<b>DVD-ROM</b> Single layer: Up to 4.7 GB Double layer: Up to 8.5 GB	
	<b>Access Times</b>	<b>DVD-ROM Single Layer</b>	< 110 ms (typical)
		<b>CD-ROM Mode 1</b>	< 110 ms (typical)
		<b>Full Stroke DVD</b>	< 230 ms (typical)
		<b>Full Stroke CD</b>	< 220 ms (typical)
	<b>Power</b>	<b>Source</b>	SATA DC power receptacle
		<b>DC Power Requirements</b>	5 VDC ± 5%-100 mV ripple p-p
		<b>DC Current</b>	5 VDC – <800mA typical, < 1600 mA maximum
	<b>Operating Environmental</b> (all conditions non-condensing)	<b>Temperature</b>	41° to 122° F (5° to 50° C)
<b>Relative Humidity</b>		10% to 80%	
<b>Maximum Wet Bulb Temperature</b>		84° F (29° C)	
<b>Operating Systems Supported</b>	Windows 8.1, Windows 8 32-bit and 64-bit, Windows 7 Professional 32-bit and 64-bit, Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows 2000, Windows XP Professional or Windows XP Home 32*. Linux®		
	No driver is required for this device. Native support is provided by the operating system.		
<b>Kit Contents</b>	9.5mm Slim DVD-ROM Drive, 5.25" ODD Bay adapter/carrier, slim SATA data/power cable, installation guide		
<b>Approvals</b>	USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport Specification Rev. 1.0, Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE, BSMI, C-Tick, VCCI, MIC, cUL, TUVT		

**NOTE:** Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.



### Technical Specifications - Controller Cards

<b>HP Thunderbolt™ 3/USB4 PCIe 3 Single-port I/O Card</b>	<b>Data Transfer Rate</b>	Supports up to 40 Gb/s* 40,000 Mb/s)
	<b>Devices Supported</b>	Thunderbolt™ certified devices
	<b>Bus Type</b>	PCIe card, Low-Profile PCIe slot
	<b>Ports</b>	One USB4 Type-C® connector (Rear)
	<b>Internal Connectors</b>	Two wire-to-board connectors
	<b>System Requirements</b>	Windows 10 or Windows 11, Intel® i5 series or higher processor, available on PCIe slot4.
	<b>Temperature - Operating</b>	50° to 131° F (10° to 55° C)
	<b>Temperature - Storage</b>	-22° to 140° F (-30° to 60° C)
	<b>Relative Humidity - Operating</b>	20% to 80%
	<b>Compliances</b>	FCC Part 15B, cULus 62368, CE Mark EN55032B/EN55024, Taiwan BSMI, Korea KCC
	<b>Operating Systems Supported</b>	Windows 11 Windows 10
	<b>Kit Contents</b>	HP Thunderbolt™ 3/USB4 PCIe 3 Single-port I/O Card, Flex IO wire-to-board module, One full height and One Low-Profile brackets, One power cable, One DisplayPort™ and GPIO (General-Purpose Input/Output) cable, Installation documentation and warranty card.

\*Maximum speed requires DisplayPort™ and PCIe aggregation.

### Technical Specifications - Networking and Communications

<b>Integrated Intel® I219LM PCIe GbE Controller (Intel® vPro® with Intel® AMT 15.0)</b>	<b>Connector</b>	RJ-45
	<b>Cabling</b>	Twin Axial Cabling up to 10m
	<b>Controller</b>	Intel® I219LM GbE platform LAN connect networking controller
	<b>Memory</b>	3 KB Tx and 3KB Rx FIFO packet buffer memory
	<b>Data Rates Supported</b>	10/100/1000 Mbps
	<b>Compliance</b>	802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az, 802.3i, 802.3u, 802.3z
	<b>Bus Architecture</b>	PCI Express and SMBus
	<b>Data Transfer Mode</b>	PCIe-based interface for active state operation (S0 state) and SMBus for host and management traffic (Sx low power state)
	<b>Power Requirement</b>	Requires 3.3V (integrated regulators for core Vdc)
	<b>Boot ROM Support</b>	Yes
	<b>Network Transfer Mode</b>	Full-duplex; Half-duplex (not supported for the 1000BASE-T transceiver)
	<b>Network Transfer Rate</b>	10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 10 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 100 Mbps 1000BASE-T (full-duplex) 1000 Mbps
	<b>Management Capabilities</b>	vPro®, WOL, auto MDI crossover, PXE, Multi-port teaming, RSS, ACPI, Advanced cable diagnostic, loopback modes, AMT 15.0 support, Circuit Breaker, VLAN, Multicast Listener Discovery (MLD)

<b>HP 1-Port 1GbE Flex 10 NIC</b>	<b>Connector</b>	RJ-45
	<b>Cabling</b>	1GbE over Category 5e (or better) up to 100m
	<b>Controller</b>	Realtek RTL8153
	<b>Data Rates Supported</b>	10/100/1000 Mbps
	<b>Compliance</b>	802.3 (LAN) 802.3u (100BASE-TX) 802.3ab (1000BASE-T) 802.3x (Ethernet Flow Control) 802.1Q (Virtual LAN) 802.3az (Energy Efficient Ethernet)
	<b>Bus Architecture</b>	USB
	<b>Power Requirement</b>	Requires 3.3V (integrated regulators for core Vdc)
	<b>Boot ROM Support</b>	Yes
	<b>Network Transfer Mode</b>	Full-duplex; Half-duplex
	<b>Network Transfer Rate</b>	10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 100 Mbps 1000BASE-T (full-duplex) 1000 Mbps
	<b>Operating Temperature</b>	32° to 131° F (0° to 55° C)
	<b>Dimensions (HxW)</b>	1.5 in x 1.5 in. x 0.75 in (3.81 cm x 3.81 cm x 1.9 cm)

### Technical Specifications - Networking and Communications

<b>Operating System Driver Support</b>	Windows 11 Windows 10 Linux®
--	------------------------------------

<b>HP 10GbE SFP+ SR Transceiver</b>	<b>Operating Temperature</b>	32°F to 113°F (0°C to 45°C)
	<b>Operating Humidity</b>	0% to 85%, noncondensing
	<b>Dimensions (HxWxD)</b>	0.47 x 0.54 x 2.19 inches
	<b>Kit Contents</b>	HP 10GbE SFP+ SR Transceiver

<b>Intel® X550-T2 2-Port 10GbE NIC</b>	<b>Connector</b>	2 RJ-45
	<b>Cabling</b>	10GbE: Cat6a (or better) up to 100m 5GbE and below: Cat5e (or better) up to 100m
	<b>Controller</b>	Intel® Ethernet Controller X550
	<b>Network Transfer Rates Supported</b>	10GbE, 5GbE, 2.5GbE, 1GbE, 100MbE
	<b>Data Path Width</b>	PCIe Gen3x4
	<b>Power Requirement</b>	11.2W (typical)
	<b>Operating Temperature</b>	32° to 131° F (0° to 55° C)
	<b>Dimensions (HxW)</b>	5.1 x 2.7 in (without brackets)
	<b>Operating System Driver Support</b>	Windows 11 Windows 10 Linux®
	<b>Kit Contents</b>	<ul style="list-style-type: none"> <li>• Intel® X550-T2 2-Port 10GbE NIC with standard height bracket attached</li> <li>• Low-profile bracket</li> <li>• Product Literature</li> </ul>

<b>Aquantia® AQN-108 1-Port 5GbE NIC</b>	<b>Connector</b>	1 RJ-45
	<b>Cabling</b>	Cat5e (or better) up to 100m
	<b>Controller</b>	Aquantia® AQC108
	<b>Network Transfer Rates Supported</b>	5Gbe, 2.5GbE, 1GbE, 100MbE
	<b>Data Path Width</b>	PCIe Gen3x1
	<b>Power Requirement</b>	3.5W (typical)
	<b>Operating Temperature</b>	32° to 131° F (0° to 55° C)
	<b>Dimensions (HxW)</b>	3.72 x 3.18 inches (without brackets)
	<b>Operating System Driver Support</b>	Windows 11 Windows 10 Linux®
	<b>Kit Contents</b>	<ul style="list-style-type: none"> <li>• Aquantia AQN-108 1-Port 5GbE NIC with standard height bracket attached</li> <li>• Low-profile bracket</li> <li>• Product Literature</li> </ul>

<b>Connector</b>	2 RJ-45
------------------	---------

### Technical Specifications - Networking and Communications

<b>Intel® I350-T2 2-Port 1GbE NIC</b>	<b>Cabling</b>	Cat5e (or better) up to 100m
	<b>Controller</b>	Intel® Ethernet I350 Controller
	<b>Network Transfer Rates Supported</b>	1GbE, 100MbE, 10MbE
	<b>Data Path Width</b>	PCIe Gen2.1x4
	<b>Power Requirement</b>	4.4W (typical)
	<b>Operating Temperature</b>	32° to 131° F (0° to 55° C)
	<b>Dimensions (HxW)</b>	2.75 x 5.5 inches (without brackets)
	<b>Operating System Driver Support</b>	Windows 11 Windows 10 Linux®
	<b>Kit Contents</b>	<ul style="list-style-type: none"> <li>• Intel® I350-T2 2-Port 1GbE NIC with standard height bracket attached</li> <li>• Low-profile bracket</li> <li>• Product Literature</li> </ul>

<b>Intel® I350-T4 4-Port 1GbE NIC</b>	<b>Connector</b>	4 RJ-45
	<b>Cabling</b>	Cat5e (or better) up to 100m
	<b>Controller</b>	Intel® Ethernet I350 Controller
	<b>Network Transfer Rates Supported</b>	1GbE, 100MbE, 10MbE
	<b>Data Path Width</b>	PCIe Gen2.1x4
	<b>Power Requirement</b>	5W (typical)
	<b>Operating Temperature</b>	32° to 131° F (0° to 55° C)
	<b>Dimensions (HxW)</b>	2.75 x 5.5 inches (without brackets)
	<b>Operating System Driver Support</b>	Windows 11 Windows 10 Linux®
	<b>Kit Contents</b>	<ul style="list-style-type: none"> <li>• Intel® I350-T4 4-Port 1GbE NIC with standard height bracket attached</li> <li>• Low-profile bracket</li> <li>• Product Literature</li> </ul>

<b>Intel® Wi-Fi 6 AX201 802.11ax, BT 5.1, M.2</b>	<b>WLAN Standards</b>	802.11-2016 and select amendments (selected feature coverage) 802.11 a,b,d,e,g,h,i,k,n,r,u,v,w,ac,ax; Fine Measurement based on 802.11-2016
	<b>Antenna</b>	2x2 Dual-Band
	<b>Bluetooth Standards</b>	5.1
	<b>Operating Temperature</b>	32° to 176° F (0° to 80° C)
	<b>Interface</b>	M.2 CNVio2
	<b>Dimensions</b>	M.2 2230
<b>Kit Contents</b>	Not Available	
<b>NOTE:</b> Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.		

<b>Intel® I225-T1 1-Port 2.5GbE NIC</b>	<b>Connector</b>	1 RJ-45
	<b>Cabling</b>	Cat5e (or better) up to 85m

### Technical Specifications - Networking and Communications

<b>*Planned to be available in Q3,2021</b>	<b>Controller</b>	Intel® Ethernet I225 Controller
	<b>Network Transfer Rates Supported</b>	2.5GbE, 1GbE, 100MbE, 10MbE
	<b>Data Path Width</b>	PCIe Gen3.1x1
	<b>Power Requirement</b>	2W (typical)
	<b>Operating Temperature</b>	32° to 158° F (0°C to 70°C)
	<b>Operating System Driver Support</b>	Windows 11 Windows 10 Linux®
	<b>Kit Contents</b>	<ul style="list-style-type: none"> <li>• Intel® I225-T1 1-Port 2.5GbE NIC with standard height bracket attached</li> <li>• Low-profile bracket</li> <li>• Product Literature</li> </ul>

<b>Z2 G8 SFF Bezel w/ Dust Filter option</b>	<b>Part Number</b>	141L1AA
	<b>Overview</b>	<p>Workstations are deployed in a variety of different ways and in different environments, from under a desk to manufacturing floors. HP Workstations designed a dust filter option to further protect the system against the ingress of dust and other particles over the life of the system. Test have shown a reduction of dust ingress of up to 32% for the HP Z2 Tower G8 Workstation platform and is cleanable and serviceable by customers. There is also a BIOS setting that will warn customer when it is time to check and clean their filters.</p>
	<b>Cleaning and servicing the dust filter</b>	<ol style="list-style-type: none"> <li>1. After removing the filter from the system bezel (dust filter can be removed without the use of tools from the front bezel), either blow it with and wash with water or use a delicate duster (feather duster) to brush off the filter then rinse it with water.</li> <li>2. Allow the filter half a day to dry at room temperature (25C at 30%-50% humidity)</li> <li>3. Temperature of water can be 0-70C, due to the dust filter meeting the SQTM 70C humidity test. Suggested water temperature for best user experience is 0-50C.</li> <li>4. Normal tap water (and most other types of water) can be used to rinse the filter. Any type of corrosive liquid is restricted.</li> </ol>
	<b>Enabling the Check Filter warning in the BIOS:</b>	<ol style="list-style-type: none"> <li>1. Customers must enable the BIOS setting once they receive their filter.</li> <li>2. To enable, do the following once you see the boot screen for your system: F10 &gt; Advanced &gt; Built-In Device Options &gt; Dust Filter</li> <li>3. Select to enable the Dust Filter replacement reminder, which can be set for 15, 30, 60, 90, 120, or 180 days. The Reminder will show during POST after the reminder timer has expired.</li> <li>4.</li> </ol> <p><b>NOTE:</b> customers who anticipate more dust ingress in their environments should set the reminder for a shorter window. Customers anticipating longer ingress can set the reminder for a longer window.</p>
	<b>BIOS Warnings</b>	<p>Large enterprise customers deploying multiple systems can centrally enable/control the BIOS warning using the WMI/BCU tool remotely to set the options below:</p> <p><b>Dust Filter</b></p> <ul style="list-style-type: none"> <li>• Disable*</li> </ul>

### Technical Specifications - Networking and Communications

- Enable

**Dust Filter Reminder (Days)**

15, 30, 60\*, 90, 120, and 180

**Z2 G8 SFF Dust Filter  
(Filter Only)****Part Number**

141LOAA

This is intended to be a replacement filter for the HP Z2 Tower G8 Workstation in the event that the original filter would need to be replaced.

### Technical Specifications – Miscellaneous Features

#### MISCELLANEOUS FEATURES

##### Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel® Wired for Management support; industry wide initiative to make Intel® architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

##### Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
  - Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
    - 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
    - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
    - 2 red + 4 white BIOS recovery is in progress
    - 3 red + 2 white Memory could not be initialized
    - 3 red + 3 white Graphics adaptor could not be found
    - 3 red + 4 white Power supply failure / not connected
    - 3 red + 5 white Processor not installed
    - 3 red + 6 white Current processor does not support an enabled feature
    - 3 red + 7 white Computer cover has been removed since last system startup
    - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
    - 4 red + 3 white System internal temperature has exceeded its threshold
    - 5 red + 2 white System controller firmware is not valid
    - 5 red + 3 white System controller detected BIOS is not executing
    - 5 red + 4 white BIOS could not complete initialization / PCA failure
    - 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
  - This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software
- 5 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal
- Blue Pull Tabs, and Quick Release Latches for easy Identification

### Summary of Changes

<b>Date of change:</b>	<b>Version History:</b>		<b>Description of change:</b>
May 13, 2021	From v1 to v2	Added	Intel Xeon W-1300 series
May 26, 2021	From v2 to v3	Changed	SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS and Social and Environmental Responsibility sections
June 11, 2021	From v3 to v4	Changed	Hard Drive Controllers section
July 15, 2021	From v4 to v5	Changed	Memory section
August 1, 2021	From v5 to v6	Changed	Graphics section
August 11, 2021	From v6 to v7	Changed	Social and Environmental Responsibility section
September 1, 2021	From v7 to v8	Changed	Memory, Optical and Removable Storage sections
October 1, 2021	From v8 to v9	Changed	Graphics section
December 1, 2021	From v9 to v10	Changed	Operating Systems, SATA Hard Drives, Optical and Removable Storage, Graphics and Input Devices sections
December 15, 2021	From v10 to v11	Changed	OPERATING SYSTEM and Social and Environmental Responsibility sections
January 1, 2022	From v11 to v12	Changed	Memory, OPERATING SYSTEM and Application Software sections
March 1, 2022	From v12 to v13	Changed	Other Hardware section
April 1, 2022	From v13 to v14	Changed	Graphics section
August 1, 2022	From v14 to v15	Changed	Optical and Removable Storage section



© 2022 HP Development Company, L.P. The information contained herein is subject to change without notice. The only warranties for HP products and services are set forth in the express warranty statements accompanying such products and services. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein. Intel, Intel Core, Pentium, Thunderbolt, vPro and Xeon are trademarks of Intel Corporation in the U.S. and other countries. Microsoft and Windows are either registered trademarks or trademarks of Microsoft Corporation in the United States and/or other countries. AMD is a trademark of Advanced Micro Devices, Inc. ENERGY STAR® is a registered trademark owned by the U.S. Environmental Protection Agency. Linux® is the registered trademark of Linus Torvalds in the U.S. and other countries. NVIDIA®, NVS and Quadro and the NVIDIA logo are trademarks and/or registered trademarks of NVIDIA Corporation in the U.S. and other countries. Red Hat® is a registered trademark of Red Hat, Inc. in the United States and other countries. SD is a trademark or registered trademark of SD-3C in the United States, other countries or both. Bluetooth is a trademark of its proprietor used by HP Inc. under license.